


# HuaQin Confidential

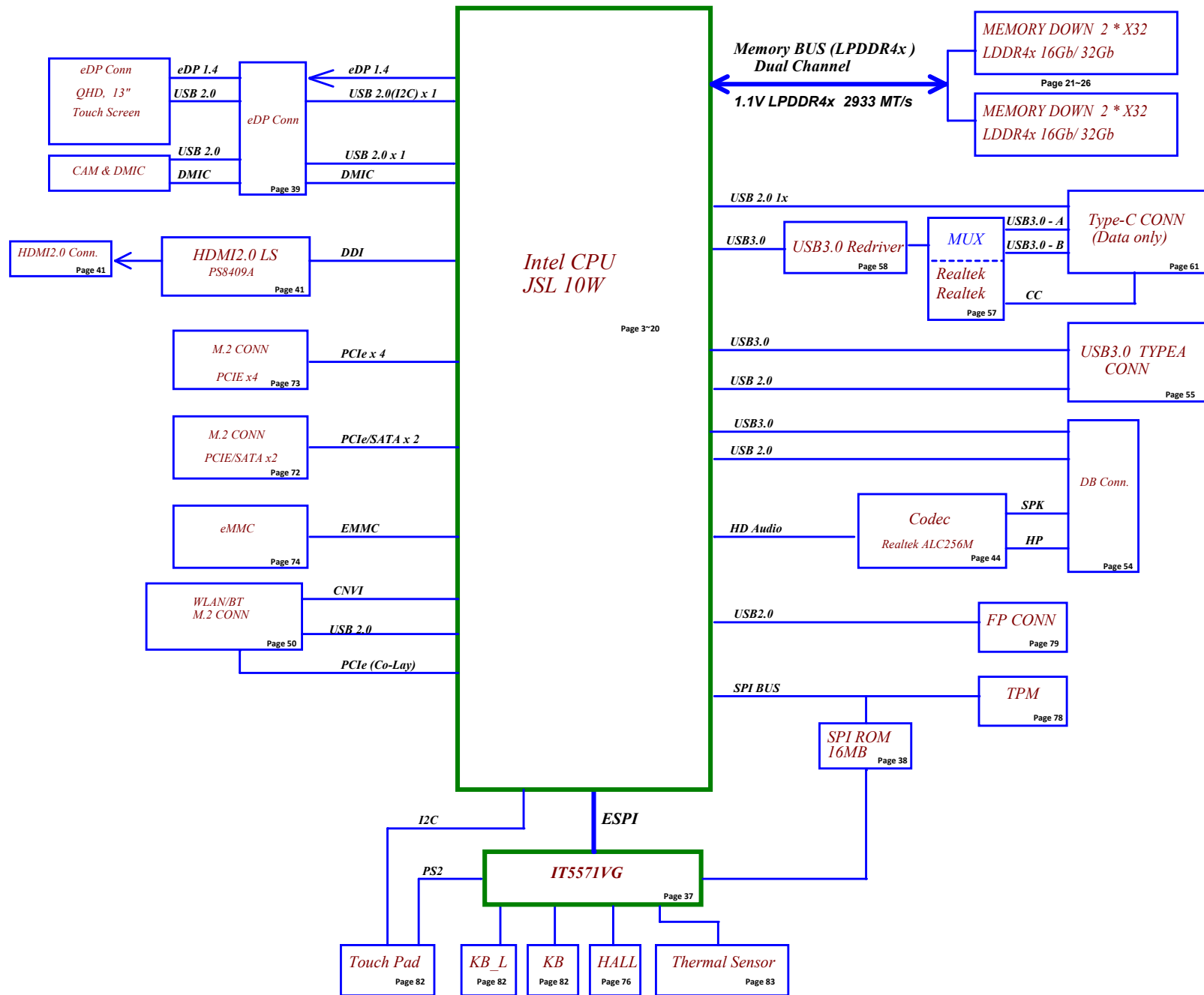
## NB2950\_MB&DB Schematics Document

### Intel JSL Lake-Processor with LPDDR4x MD

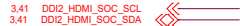
### REV1.0

### 2020-0622

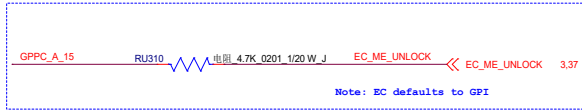
Author		 HUAQIN 华勤通信	Huaqin Telecom Technology Com.,Ltd.	
Reviewer		Page name: Cover page		
Approver		Size: A4	Project Name: NB2950-JSL	REV: V1.0
		Date: Monday, September 28, 2020	Sheet: 1	of 110



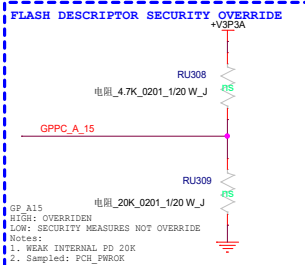
## EDP




Other



### Strap pin

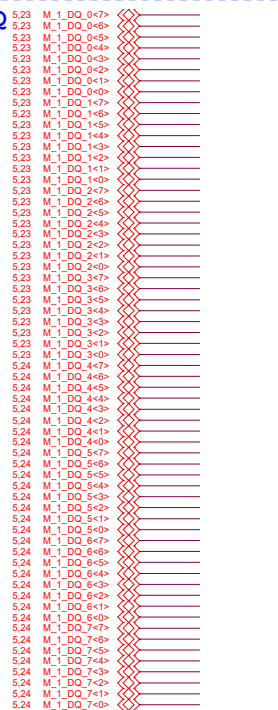


		<b>Huaqin Telecom Technology Co., Ltd.</b>	
<b>Page name: JSL-SOC(DISPLAY)</b>			
<b>Size:</b> A4	<b>Project Name:</b> NB2950-JSL	<b>REV:</b> V1.0	
<b>Date:</b> Monday, September 28, 2020	<b>Sheet:</b> 3	<b>of</b> 110	

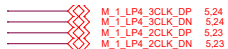


**DDR = LPDDR4/4X**

LP4/4X\_DQ



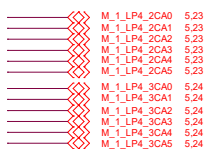
LP4/4X\_CLK



LP4/4X CEK



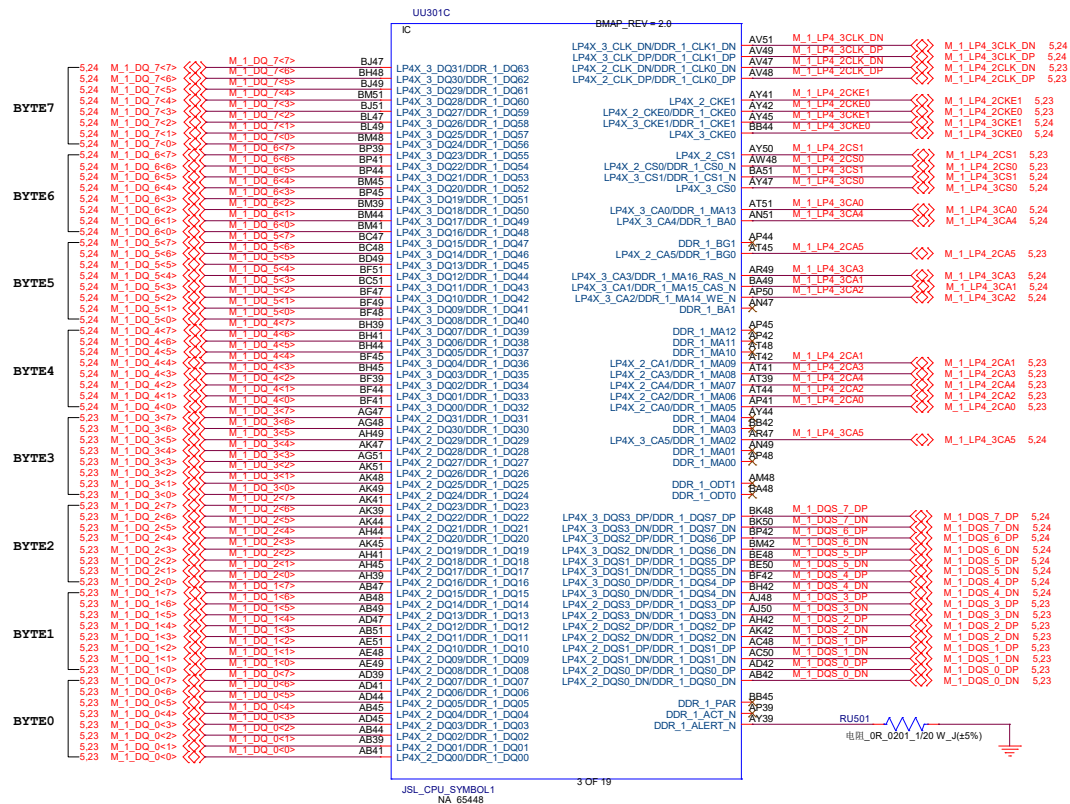
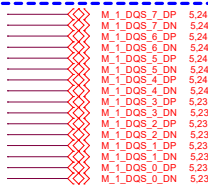
LP4/4X CA



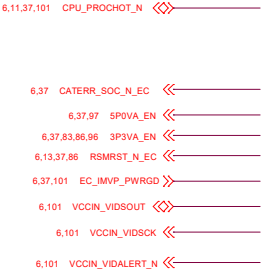
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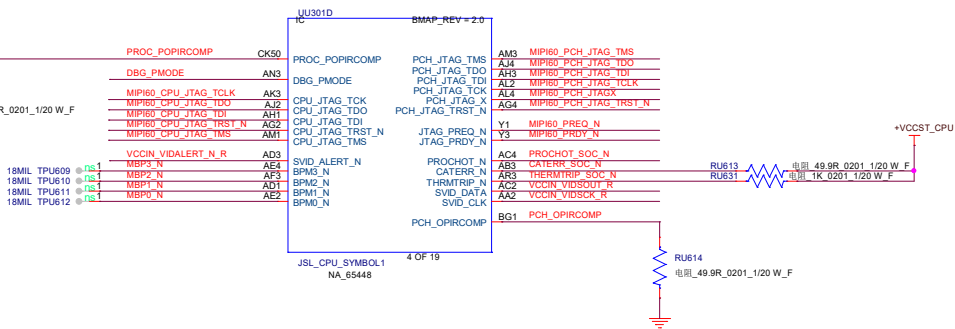
LP4/4X\_DQS



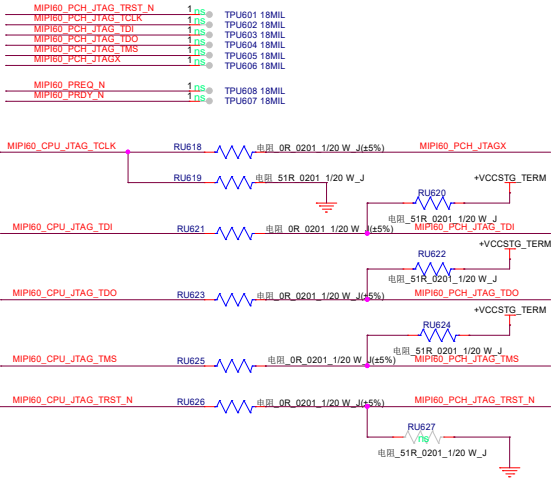
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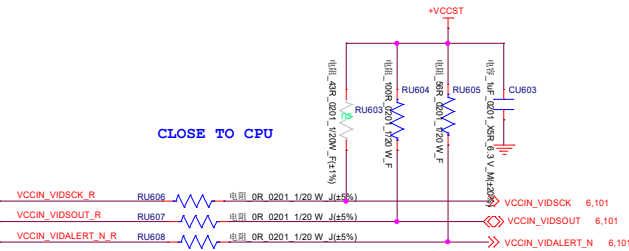
SOC



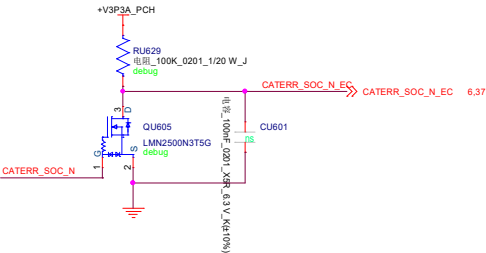
MIPI\_60



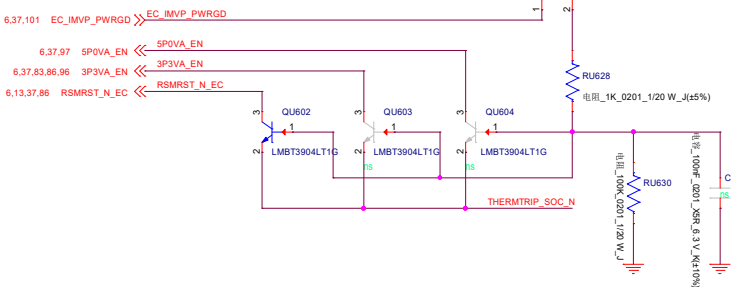
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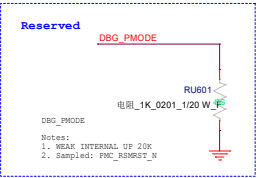
SOC\_CATERR(Reserved to EC)



SOC\_THERMTRIP



Strap



Off-Page

SPI



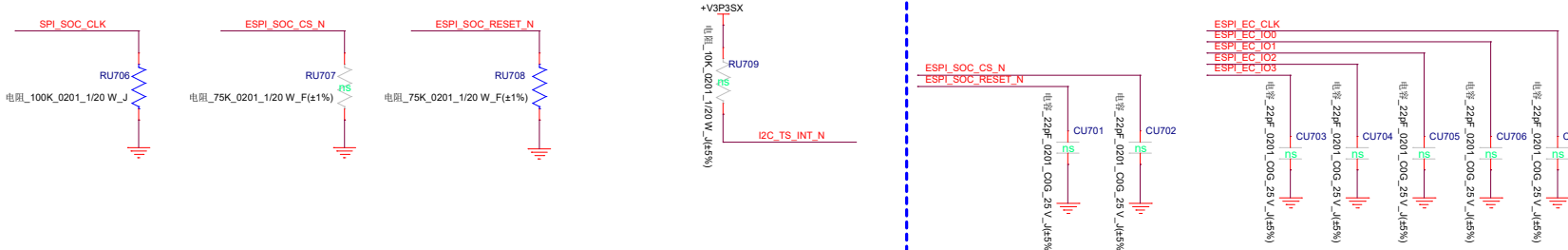
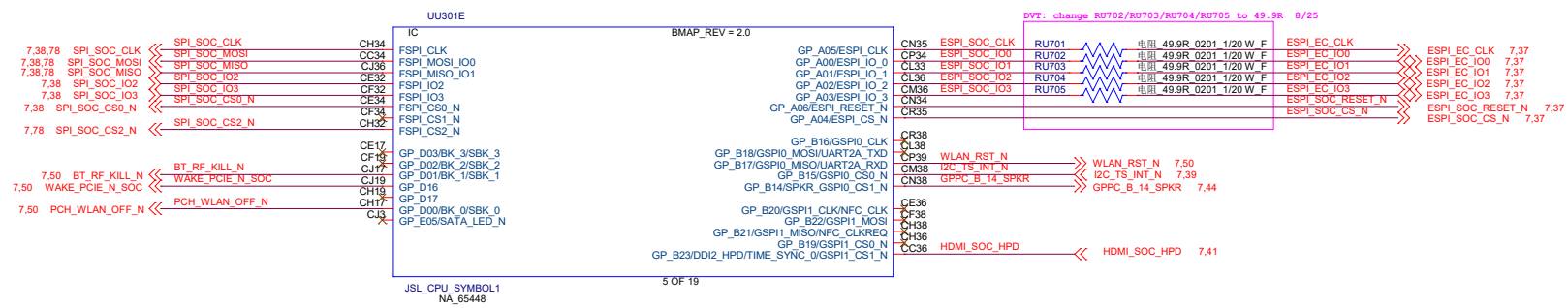
ESPI



Other



SOC



$$\overline{I2C}$$

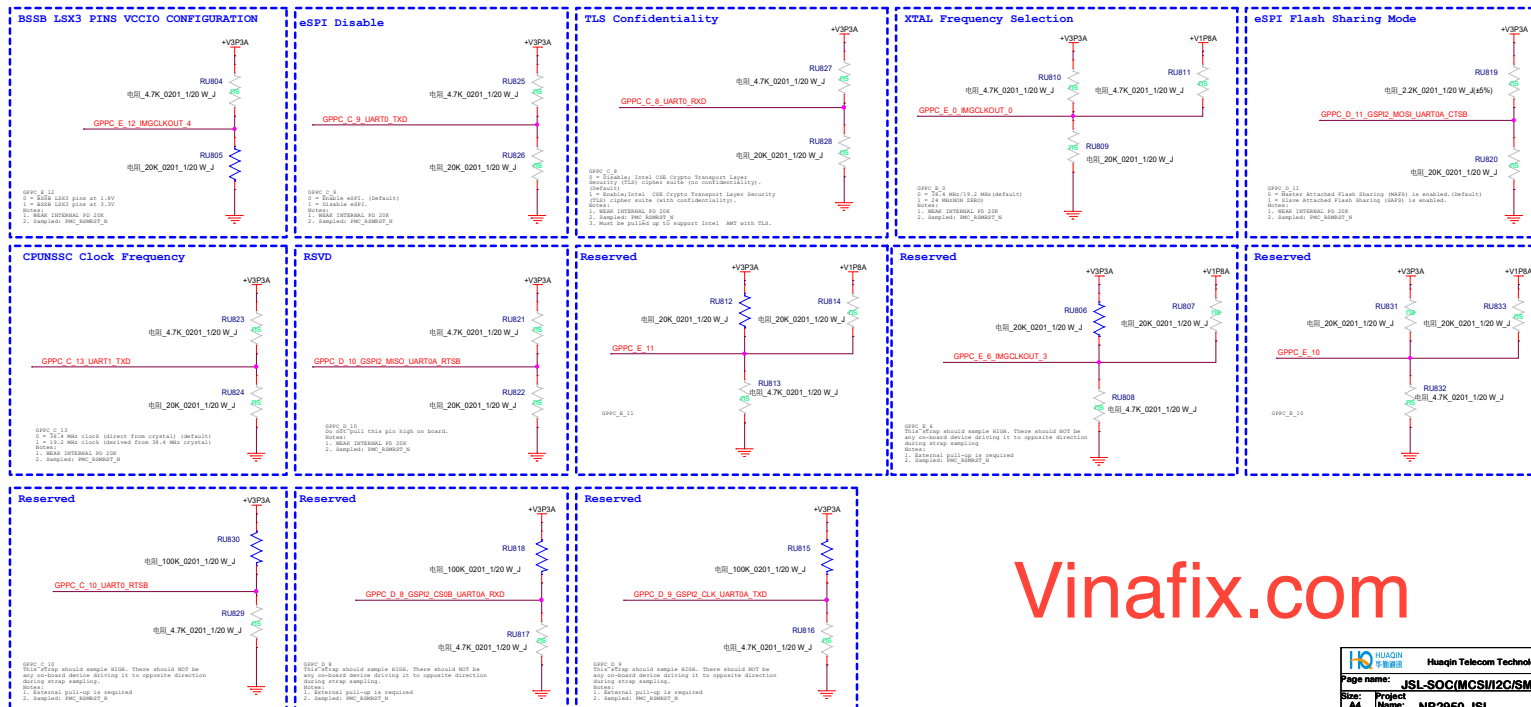

## SMBUS

1

Touch Pad



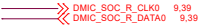
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 BOB LONG DENY





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DMIC\_0



DMIC\_1

HDA

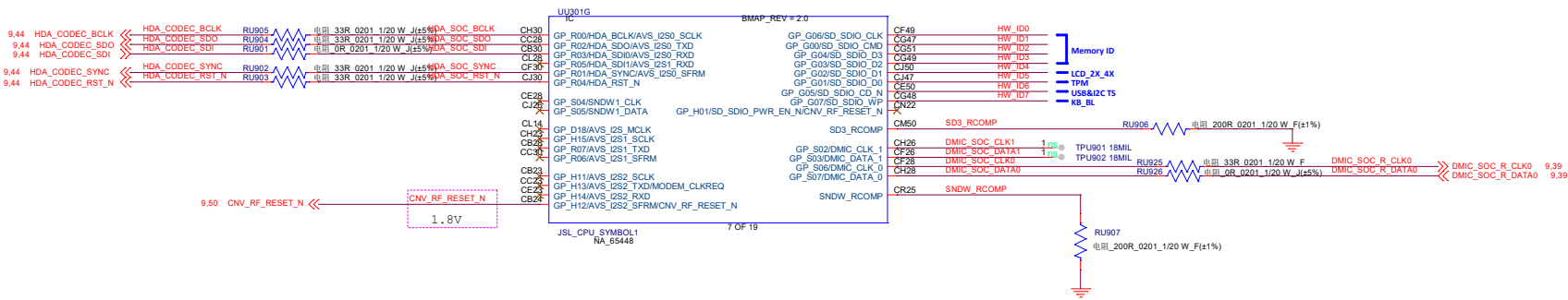


CNVI

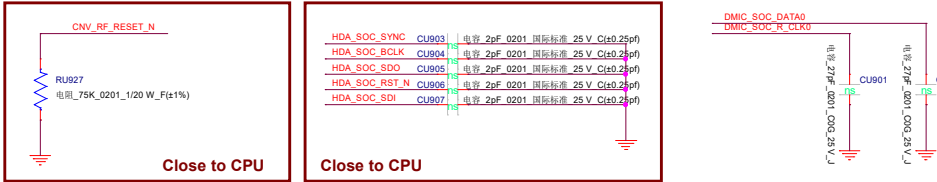
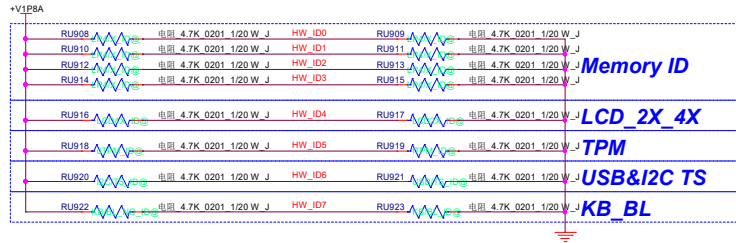


Other

SOC

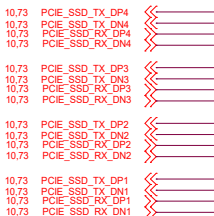


HWID

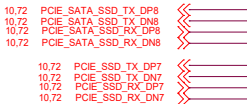


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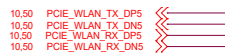
PCIE\_SSD x 4



PCIE\_SSD x 2



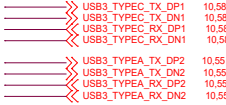
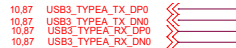
PCIE\_WLAN



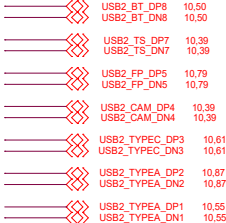
PCIE\_LAN



USB3.2



USB2.0

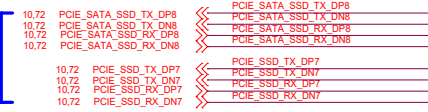


Other



SOC

SSD x2



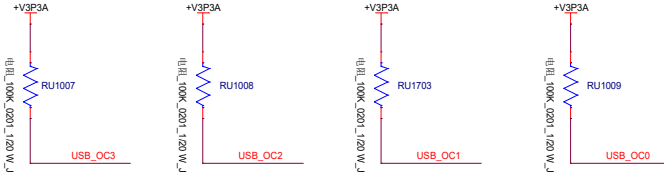
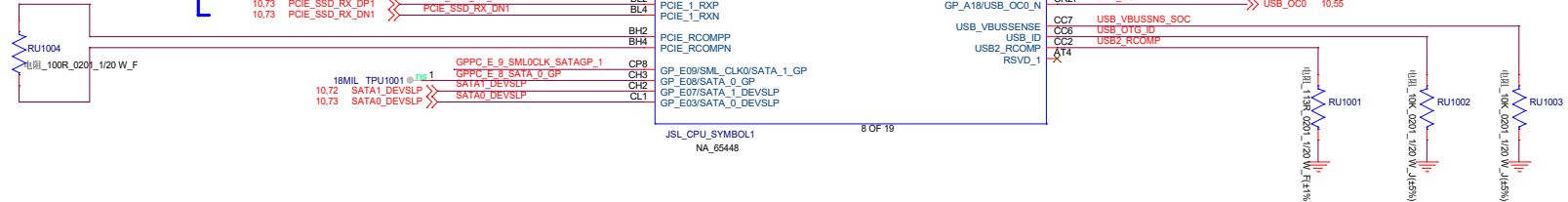
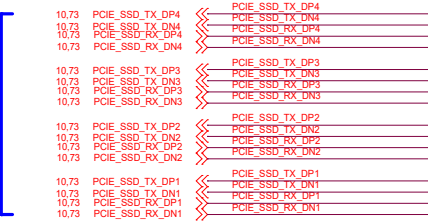
DB\_TypeA@USB3.1



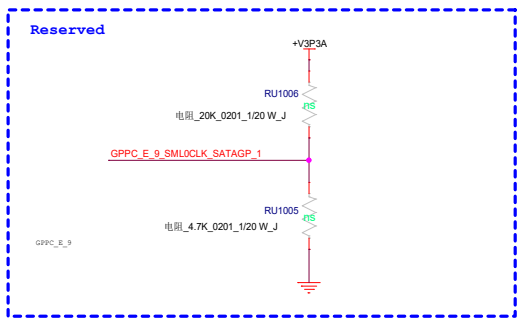
WLAN



SSD x4

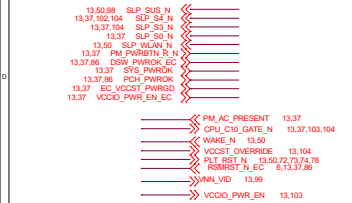


STRAP

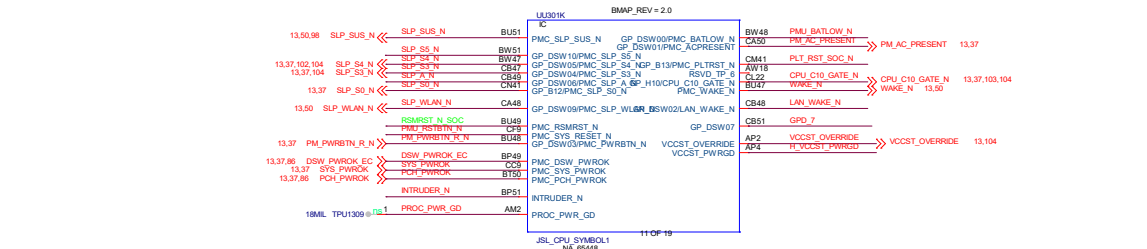




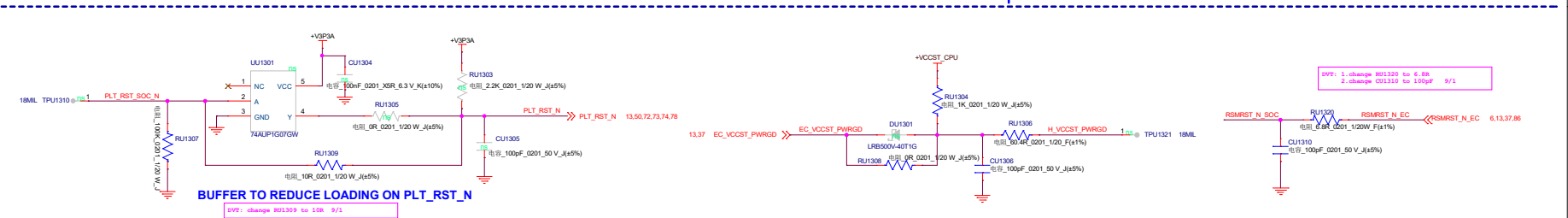
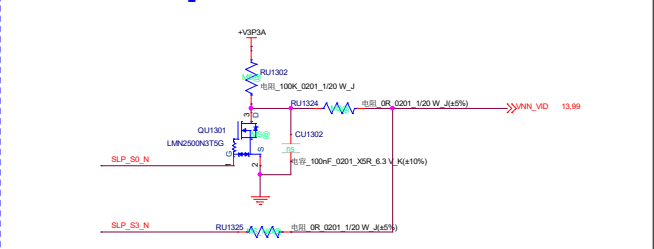




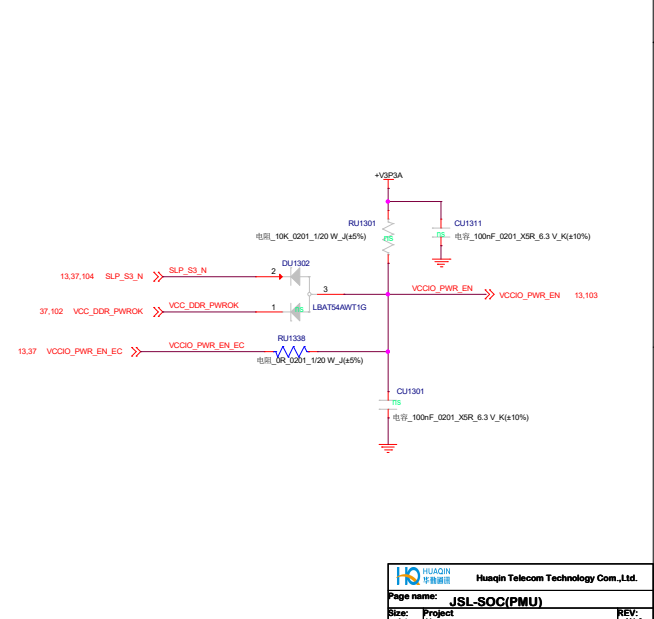
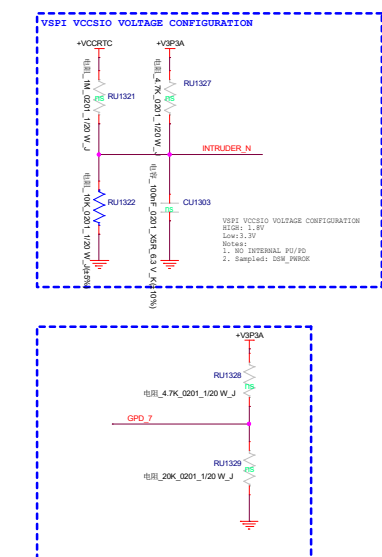
## SOC



## Modern standby



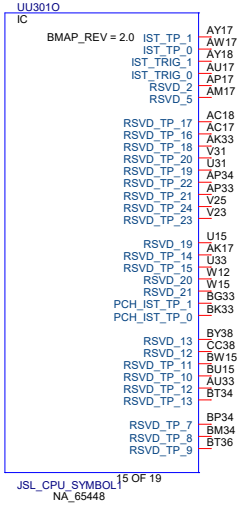
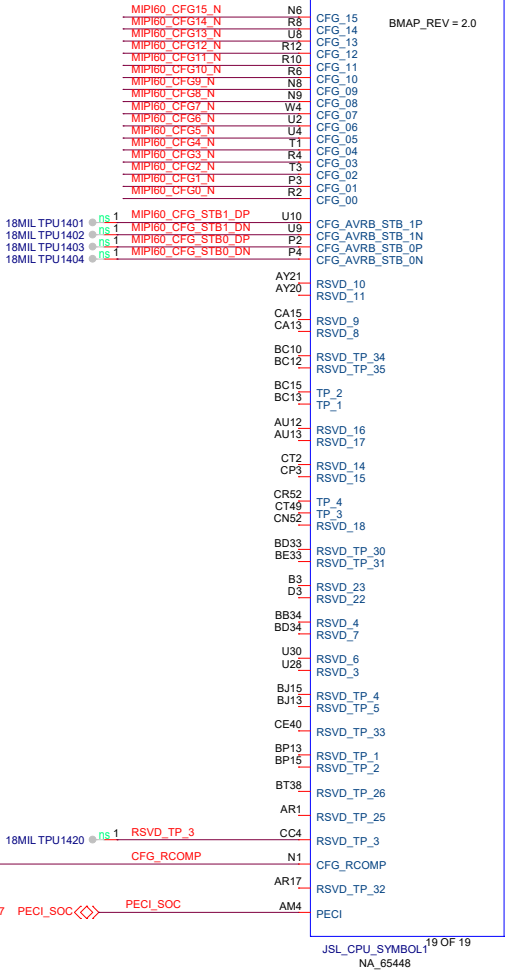
## Strap



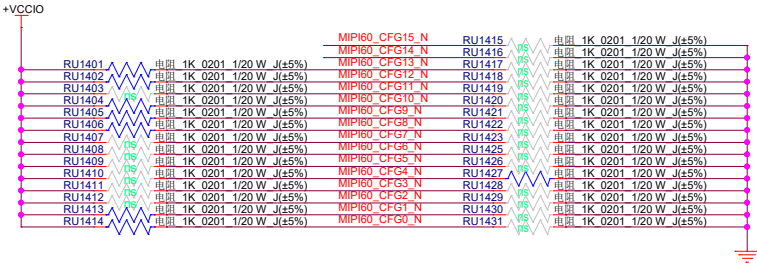
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RESERVED SIGNALS

14.37 PECL\_SOC



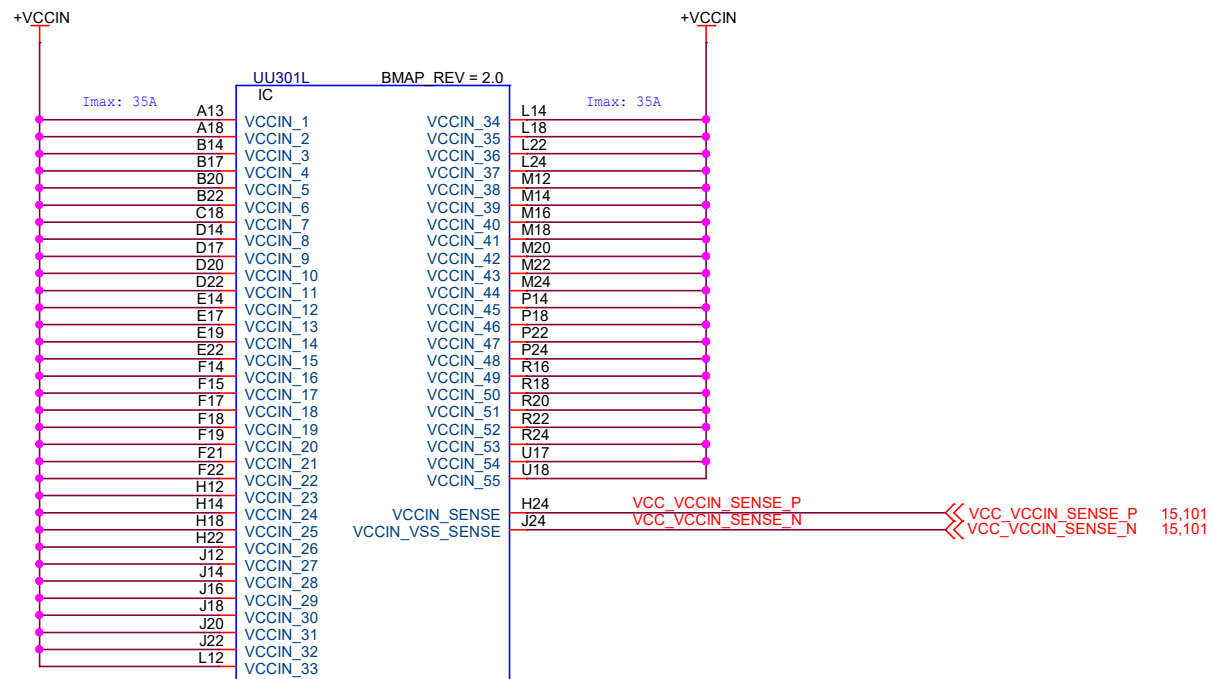
CFG Signals Functionality and Termination



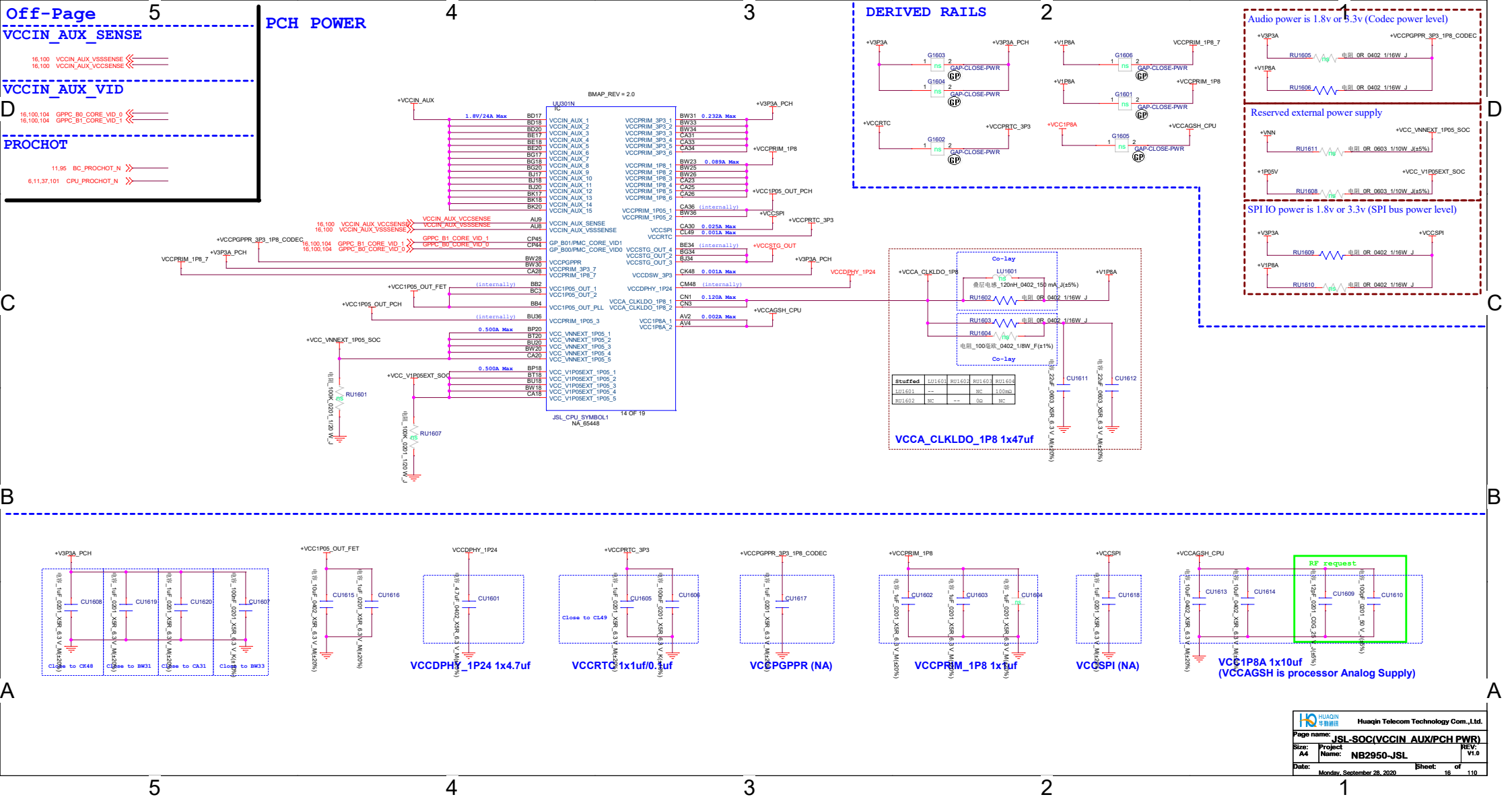
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VCCIN\_SENSE

VCC\_VCCIN\_SENSE\_P 15,101  
VCC\_VCCIN\_SENSE\_N 15,101

CPU POWER



JSL\_CPU\_SYMBOL112 OF 19  
NA\_65448

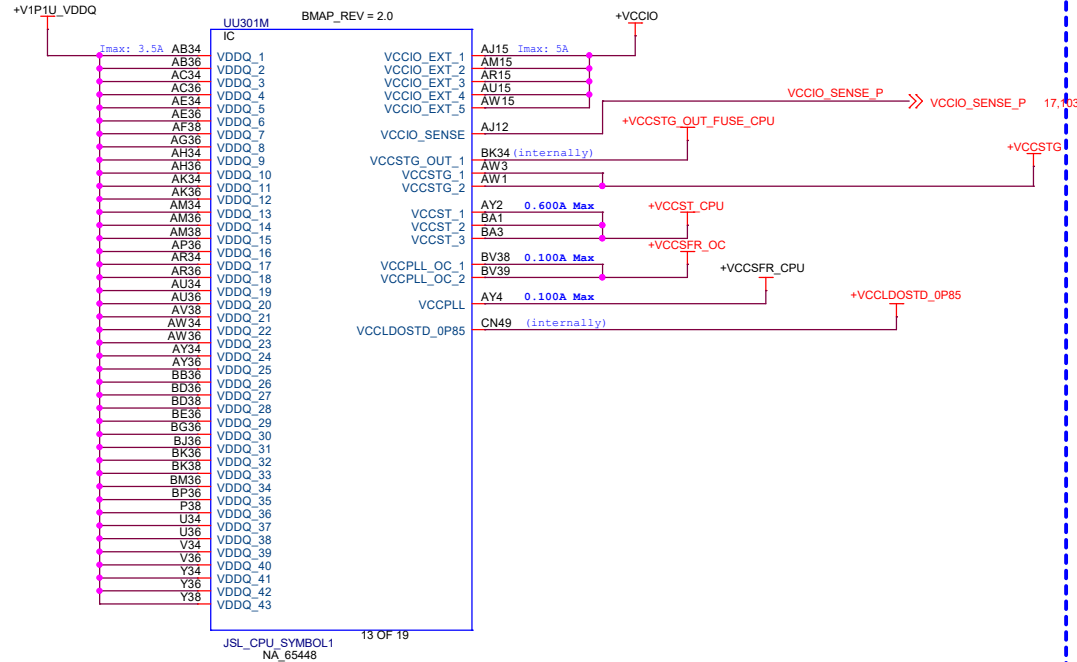




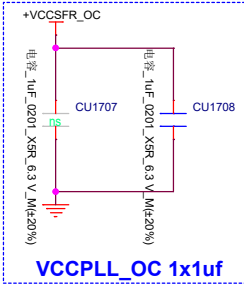
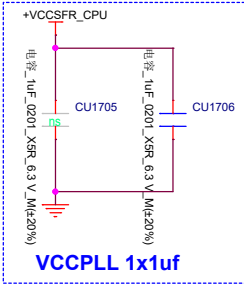
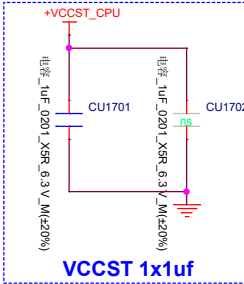
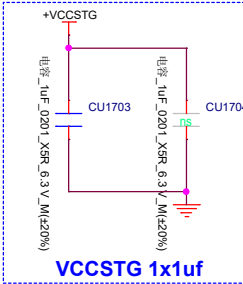
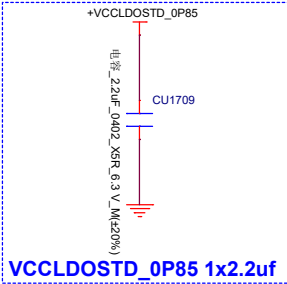
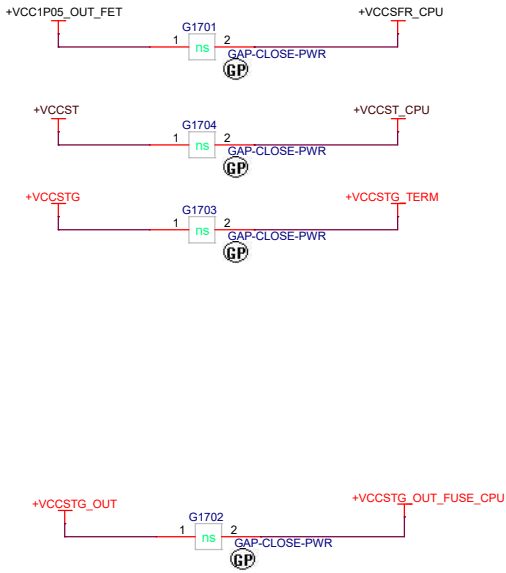
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VCCIO\_SENSE


VCCIO\_SENSE\_P 17.103

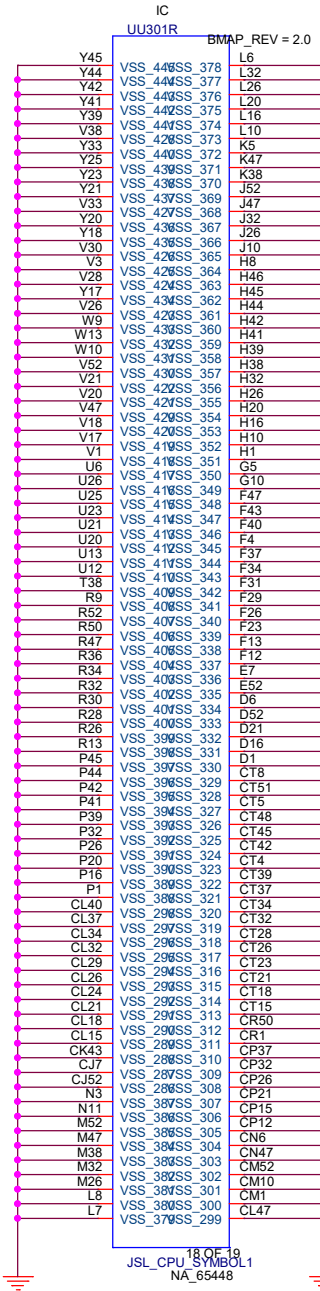
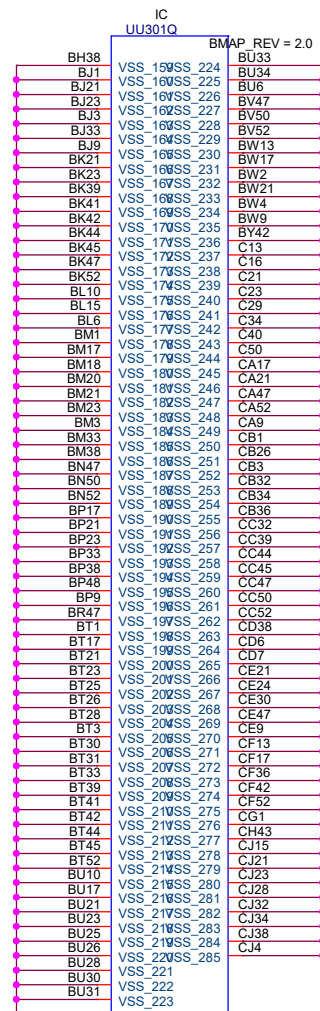
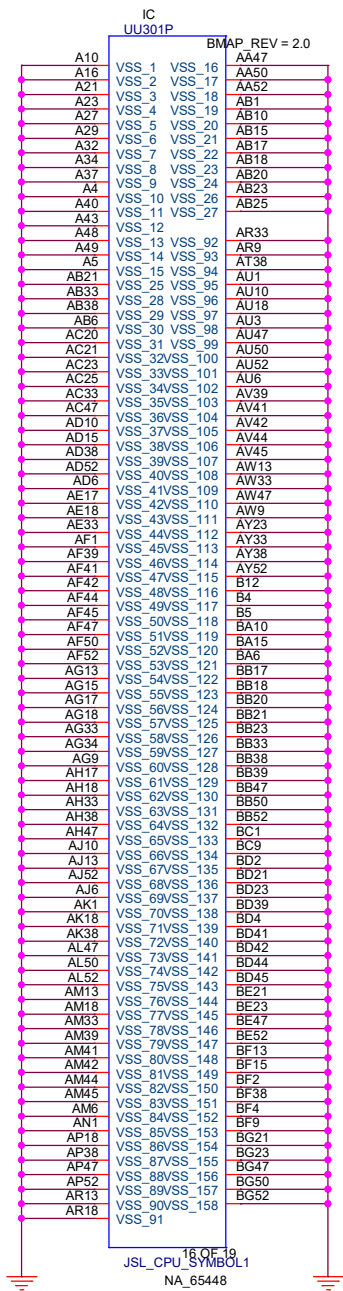
CPU POWER



DERIVED RAILS

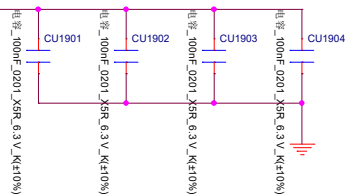


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Page name: JSL-SOC(VCC/VDDQ)			
Size: A4	Project Name: NB2950-JSL	REV: V1.0	
Date: Monday, September 28, 2020	Sheet: 17		of 110

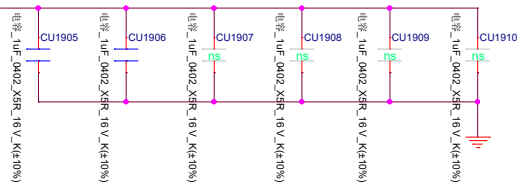


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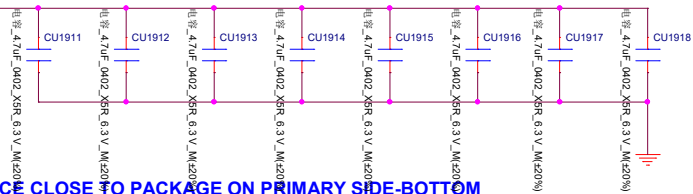
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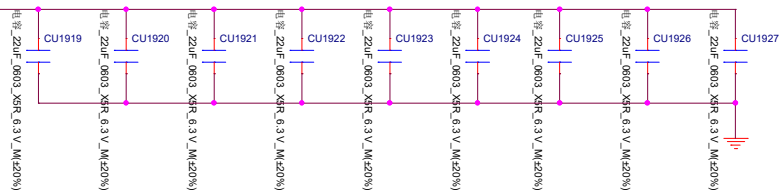
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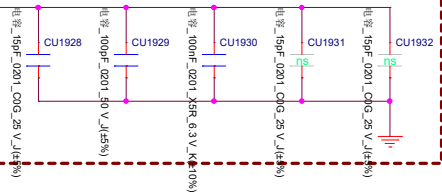
PLACE THESE CAPS UNDERNEATH BGA AREA--Top



PLACE CLOSE TO PACKAGE ON PRIMARY SIDE-BOTTOM



RF

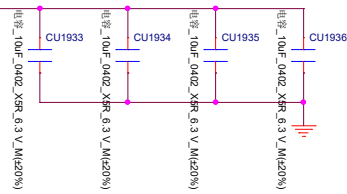


+VCCIN

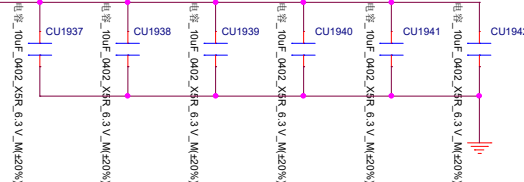
	PDG	S1
0.1uF	4	4
1uF	2	2
22uF	7+2(NC)	7+2(NC)
4.7uF	4+4(NC)	4+4(NC)
330uF	1	1

+VCCIO

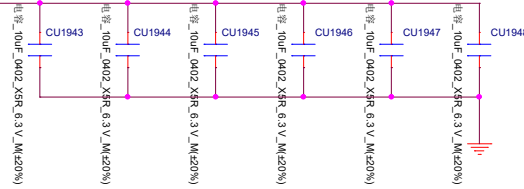
PLACE THESE CAPS UNDERNEATH BGA AREA---Top



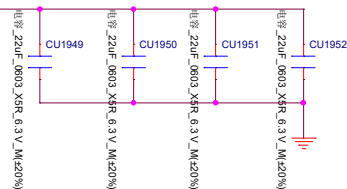
PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



+VCCIO

	PDG	S1
10uF	12+4	16
22uF	4	4

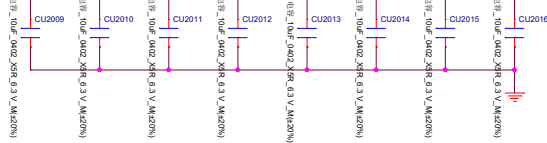
## +VCCIN\_AUX

	PDG	S1
2.2uF	4+4(NC)	4+4(NC)
10uF	4+4(NC)	4+4(NC)
22uF	4(NC)	22+4(NC)
47uF	8	0

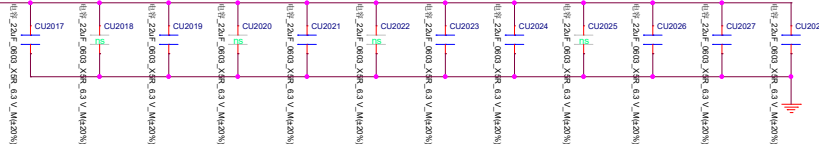
### PLACE THESE CAPS UNDERNEATH BGA AREA



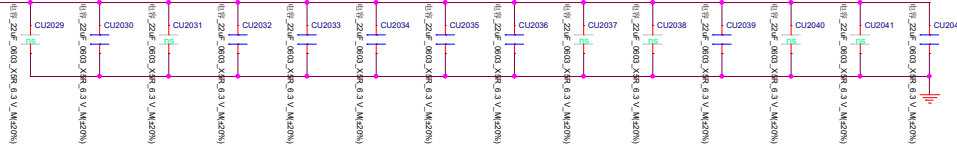
### PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



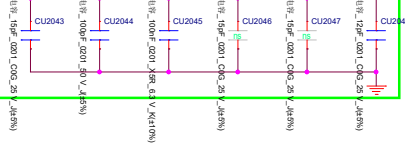
### PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



### PLACE CLOSE TO PACKAGE ON PRIMARY SIDE



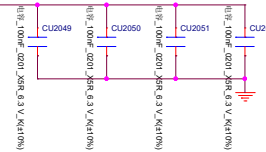
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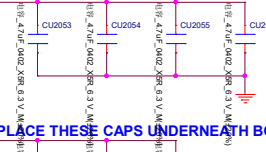
## +VDDQ\_CPU

	PDG	S1
1uF	14	14
10uF	6+1 (NC)	7
22uF	3	3
4.7uF	2+2 (NC)	4
0.1uF	2+2 (NC)	4

### PLACE THESE CAPS UNDERNEATH BGA AREA



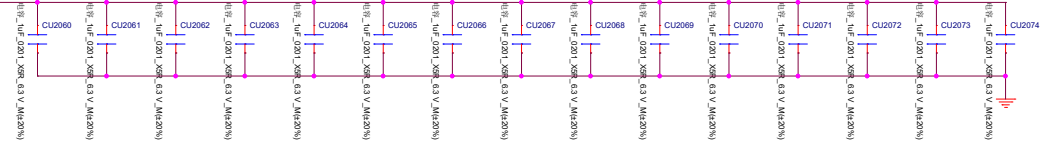
### PLACE THESE CAPS UNDERNEATH BGA AREA



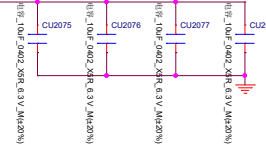
### PLACE THESE CAPS UNDERNEATH BGA AREA



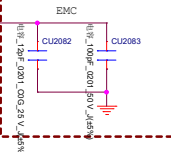
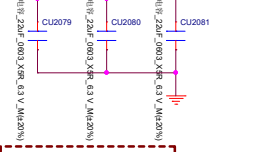
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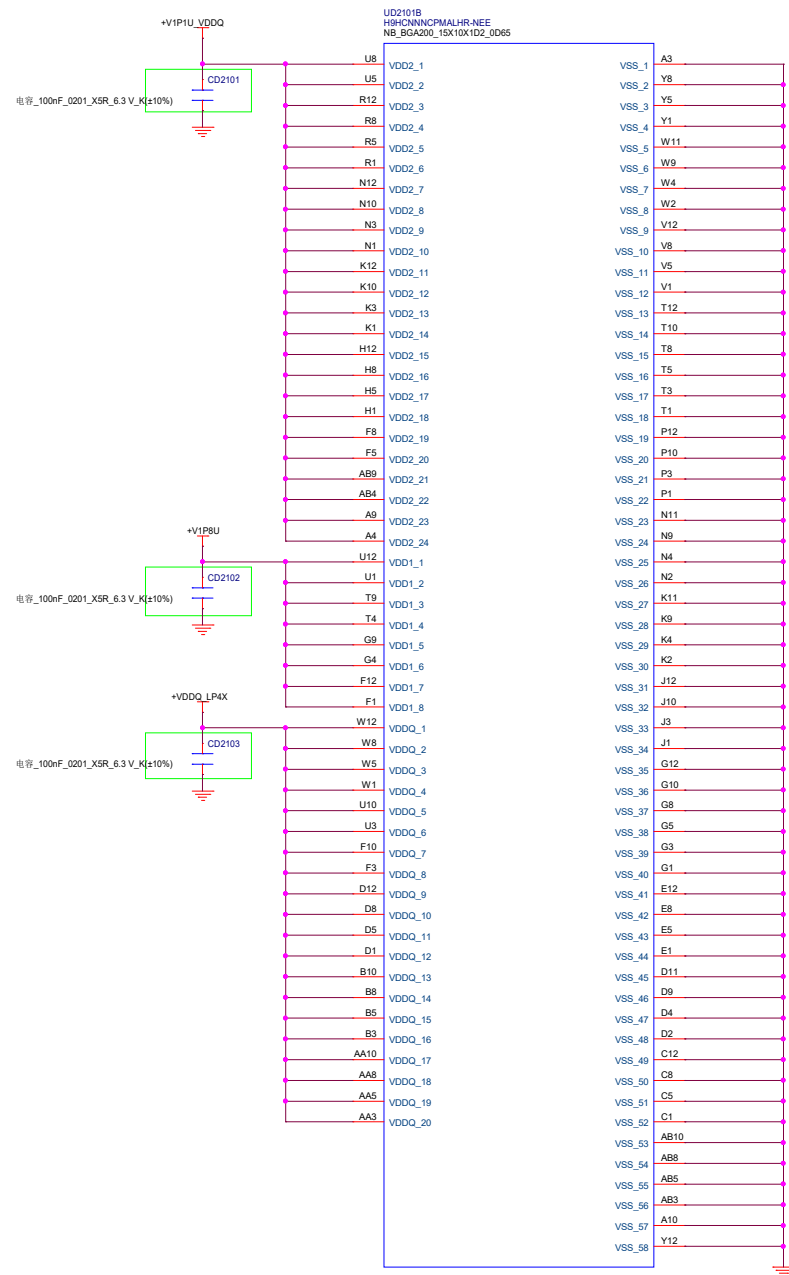
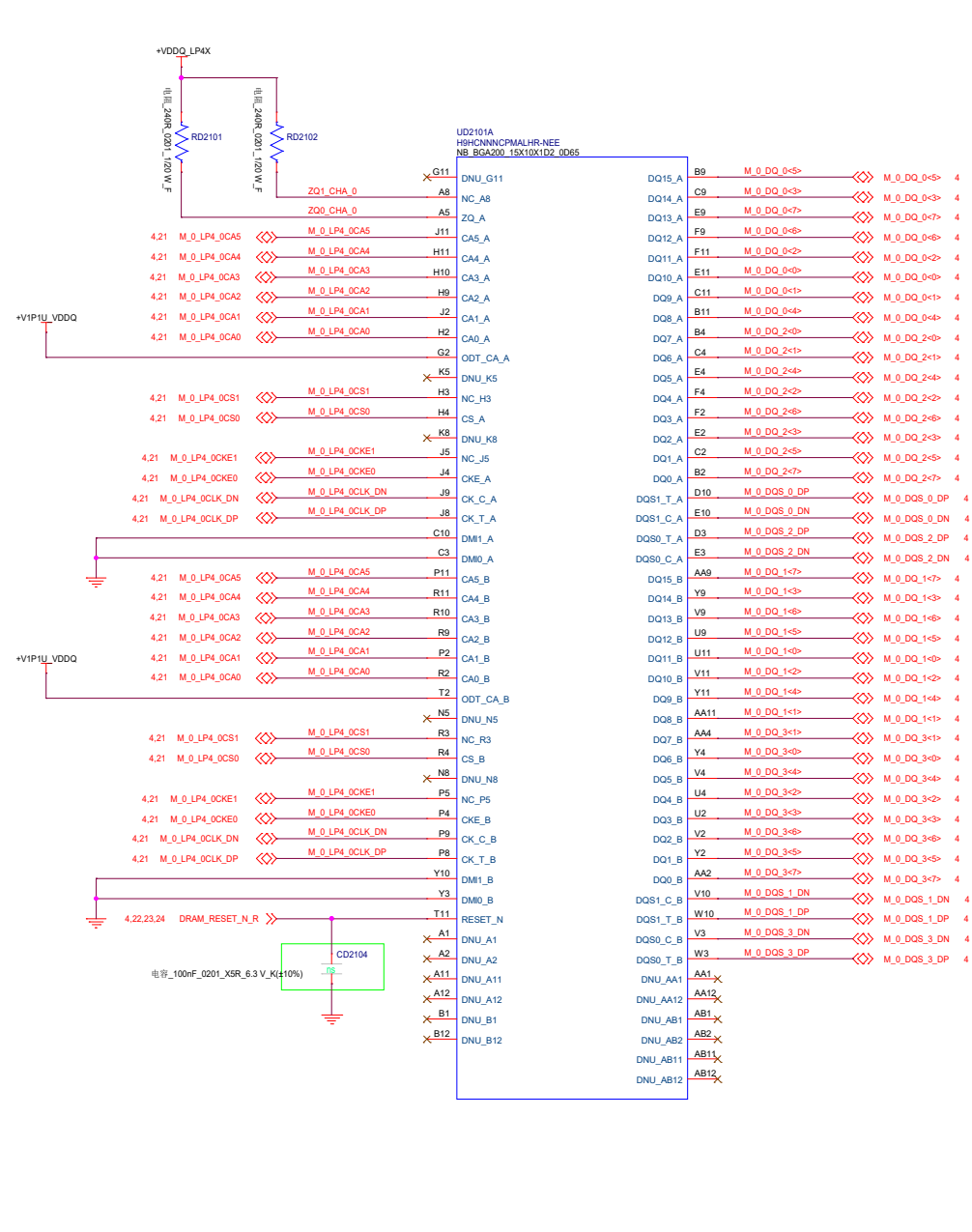


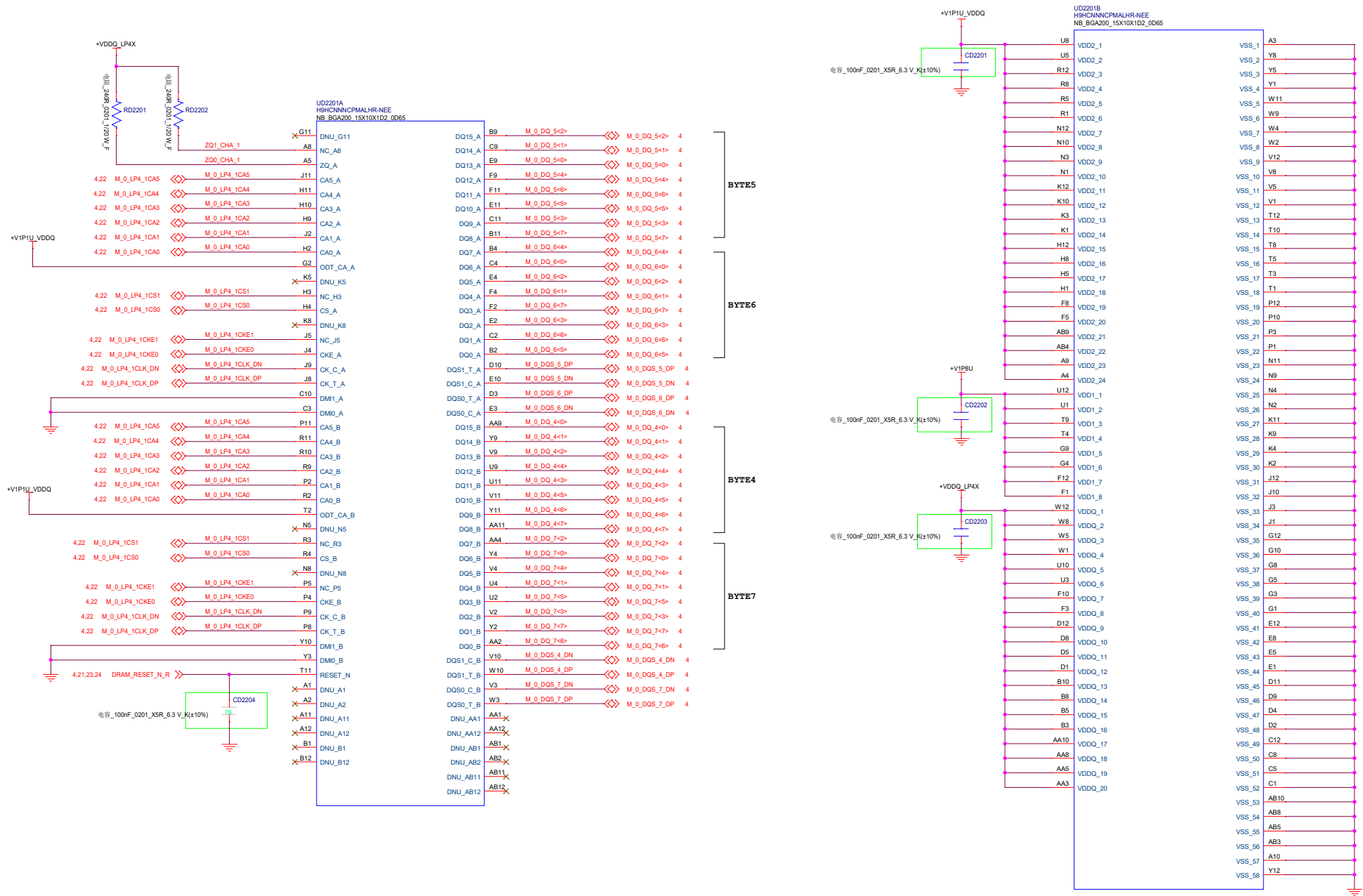
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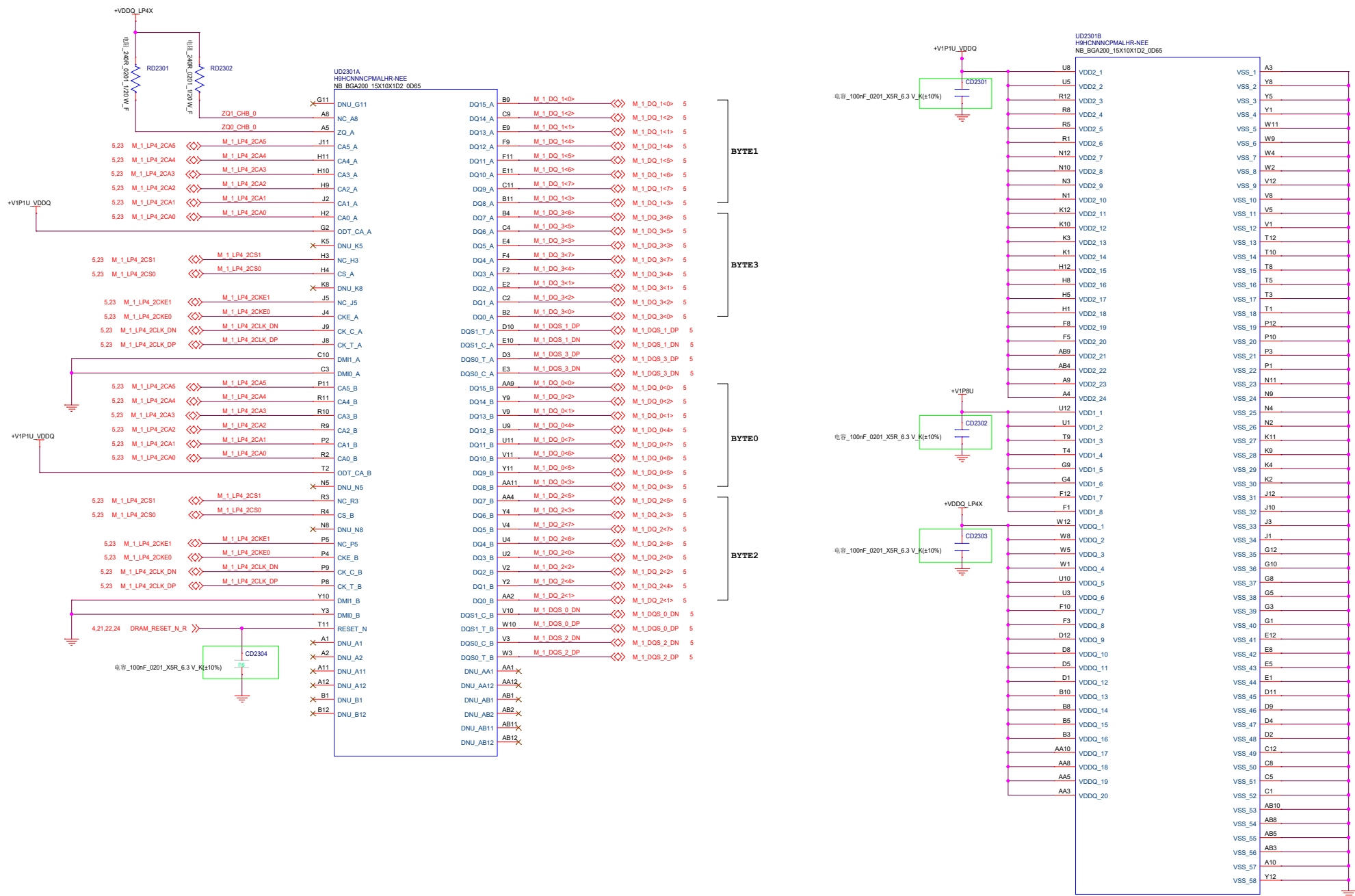


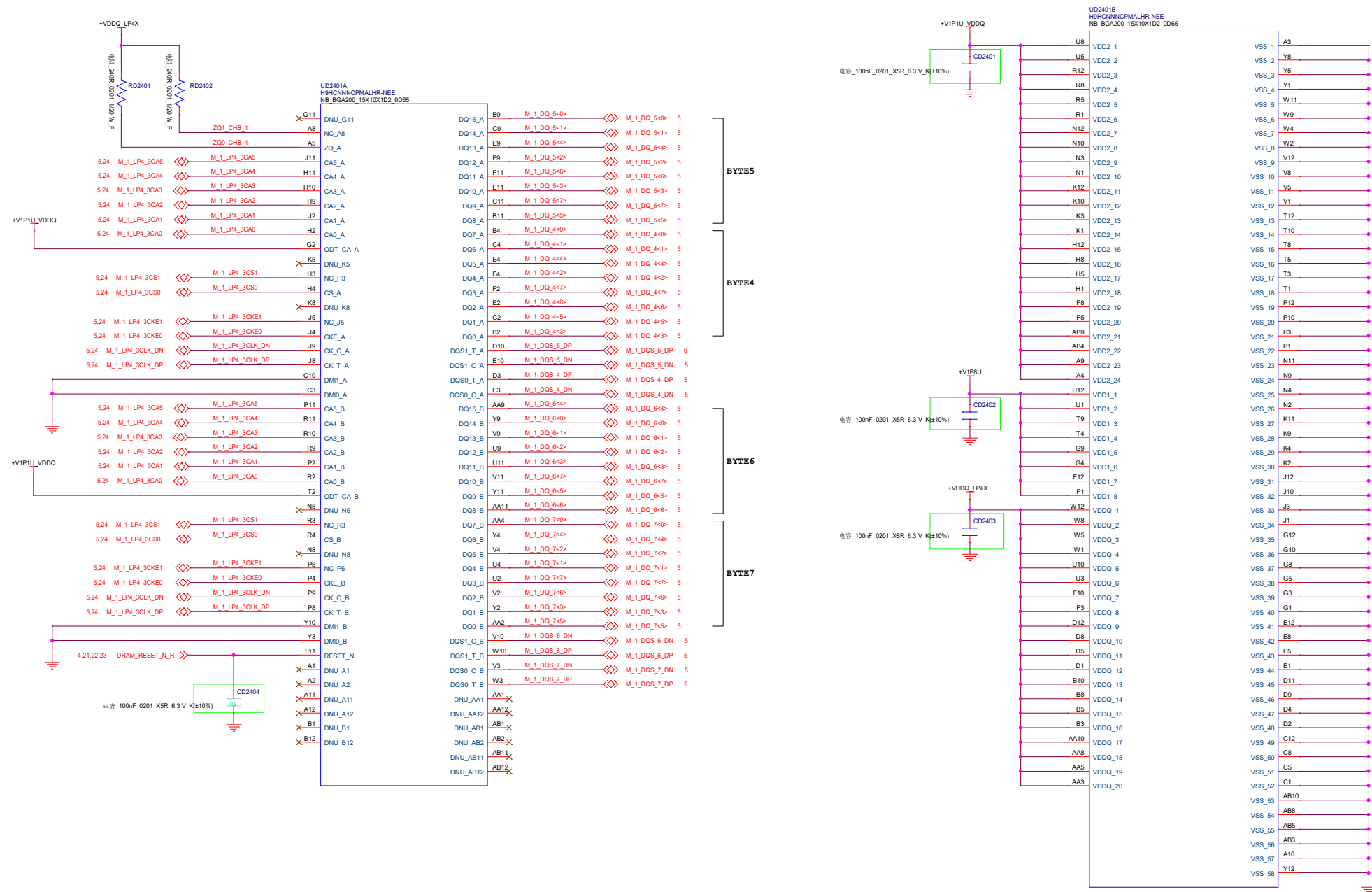
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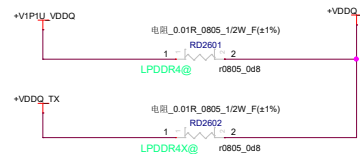
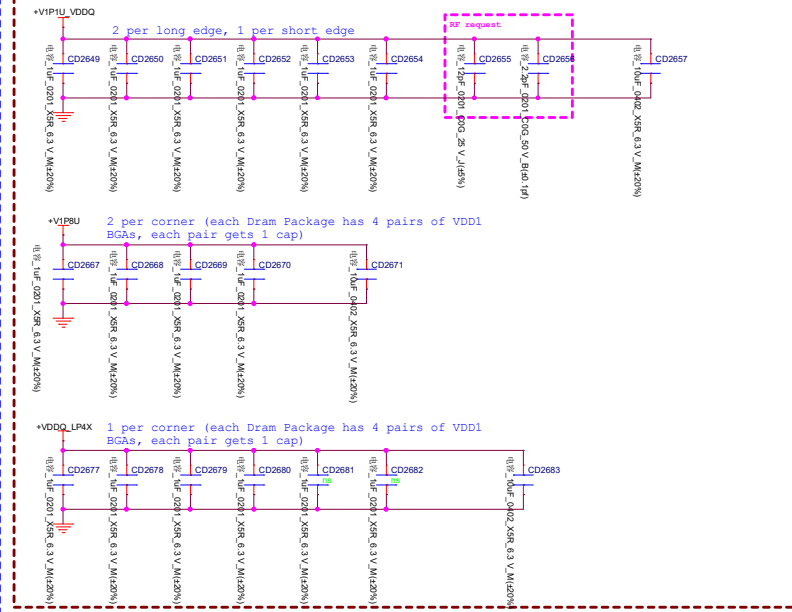
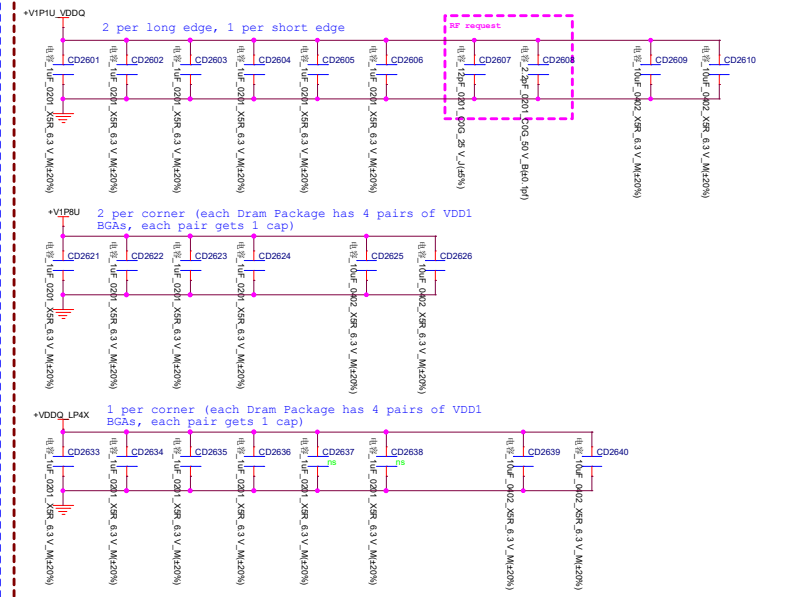




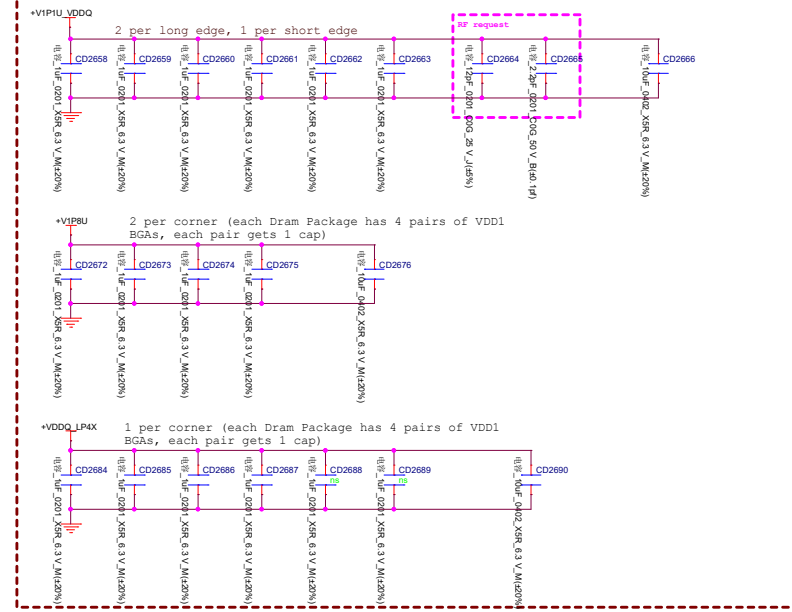
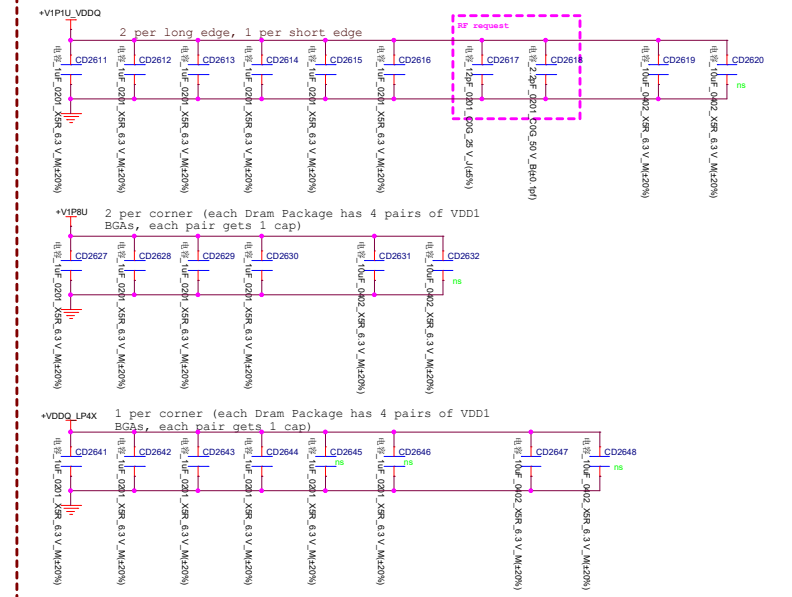




## DECOUPLING CAPACITORS FOR LPDDR4x CHANNEL A



## DECOUPLING CAPACITORS FOR LPDDR4x CHANNEL B



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1





5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

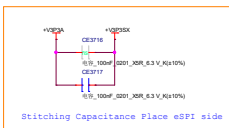
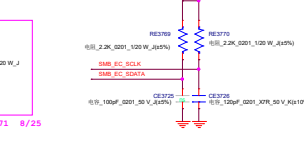
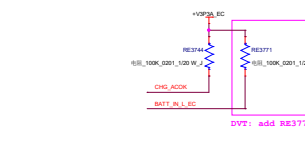
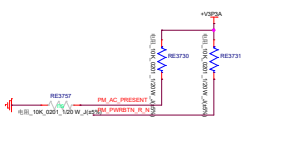
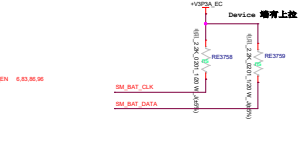
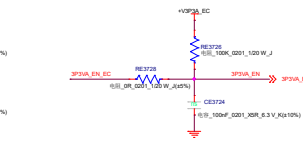
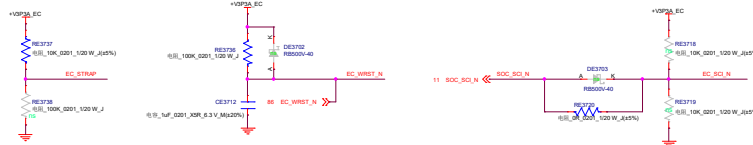
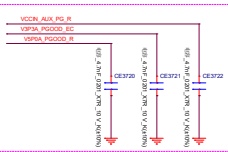
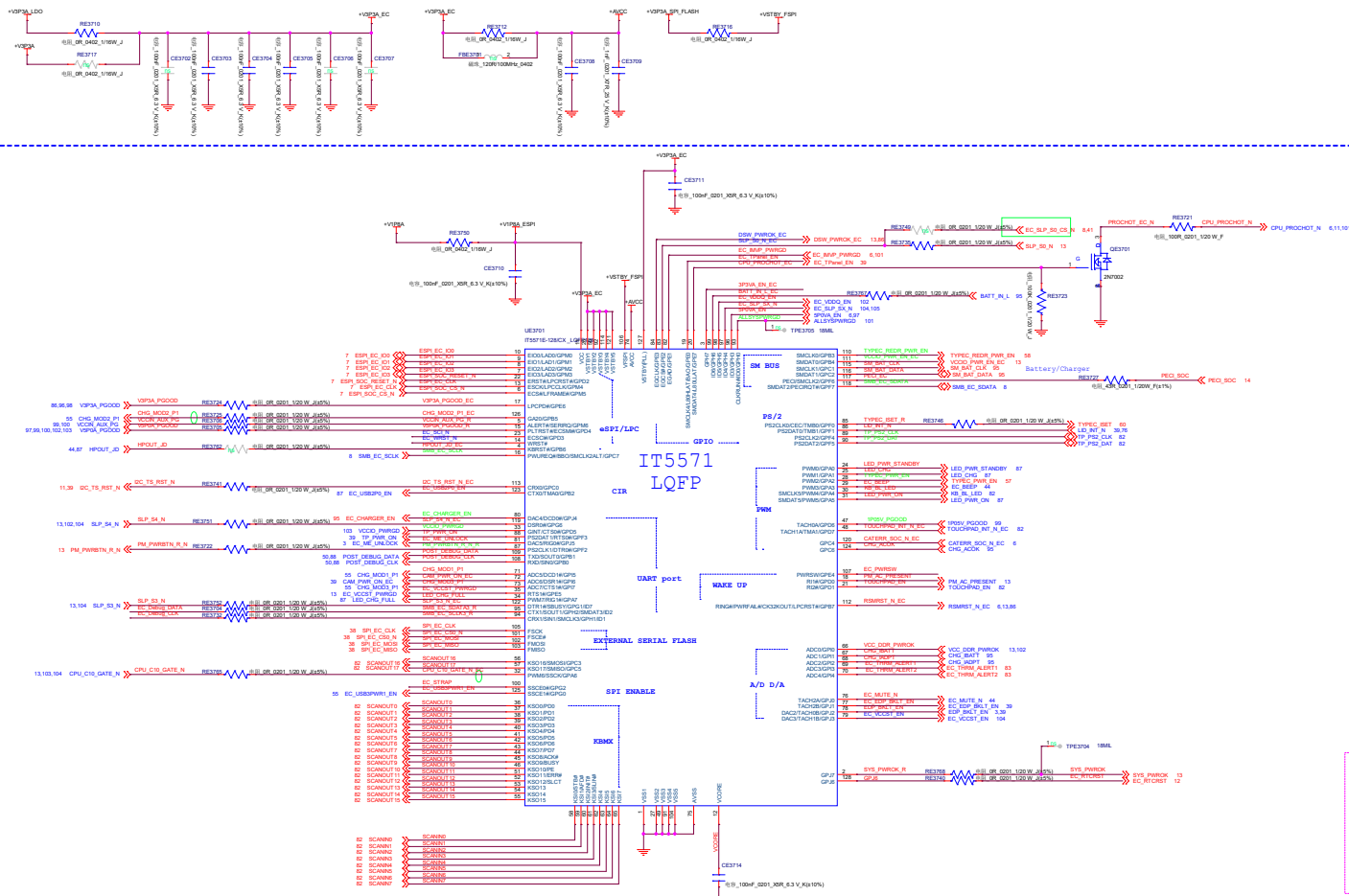


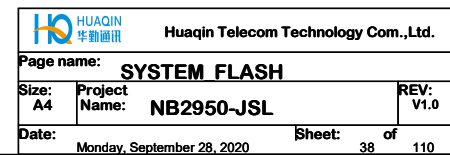
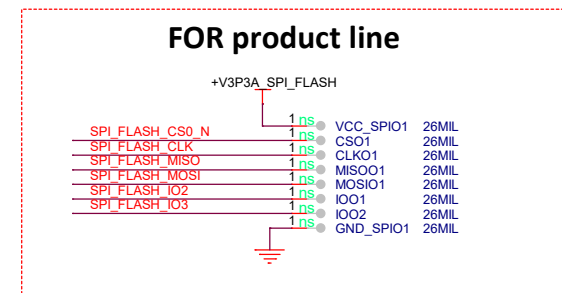




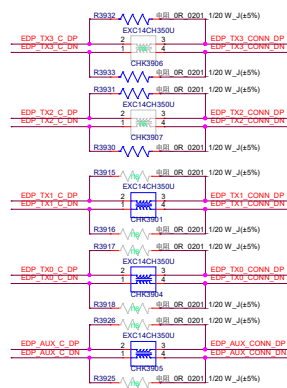
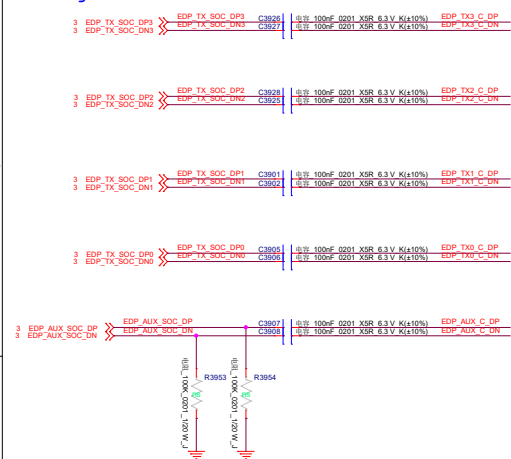
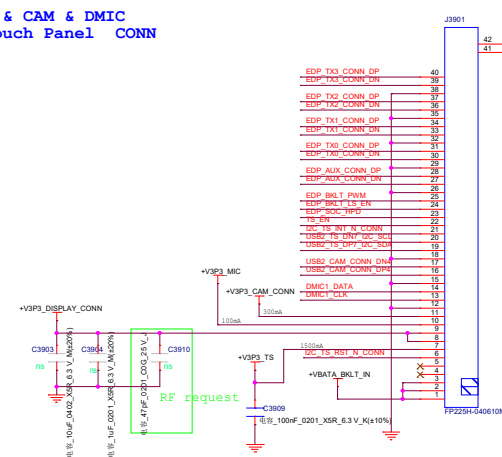
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

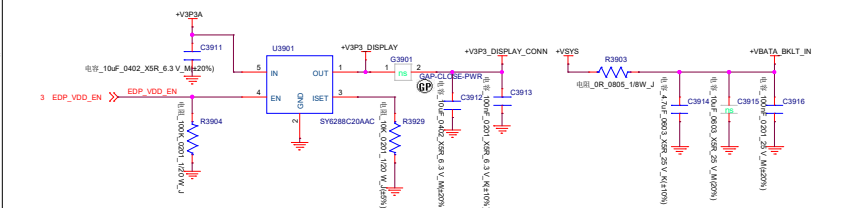




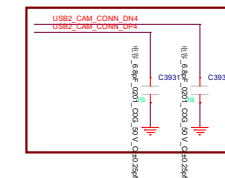
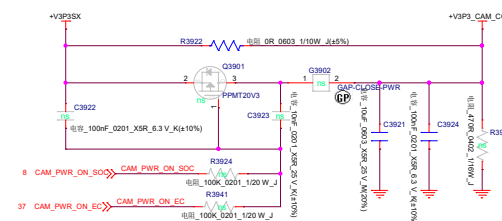
eDP Signal

eDP & CAM & DMIC  
& Touch Panel CONN

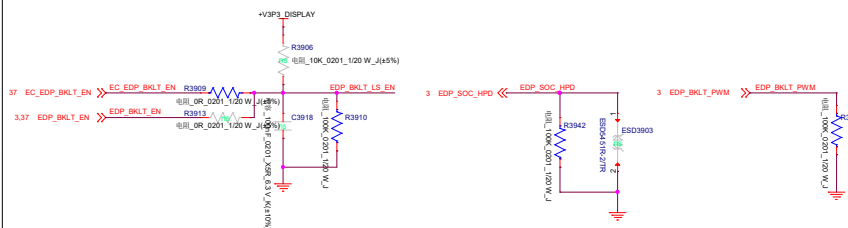
## eDP VCC &amp; BL Power



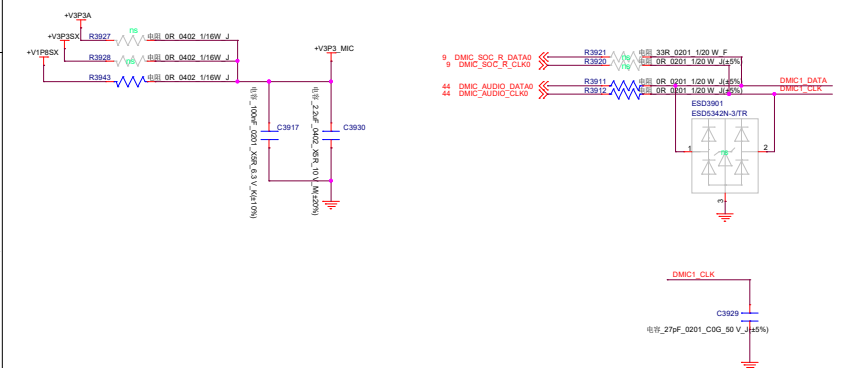
## CAM Power



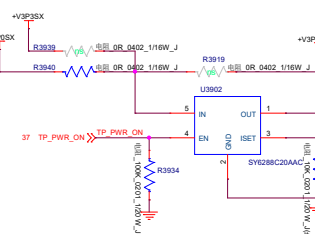
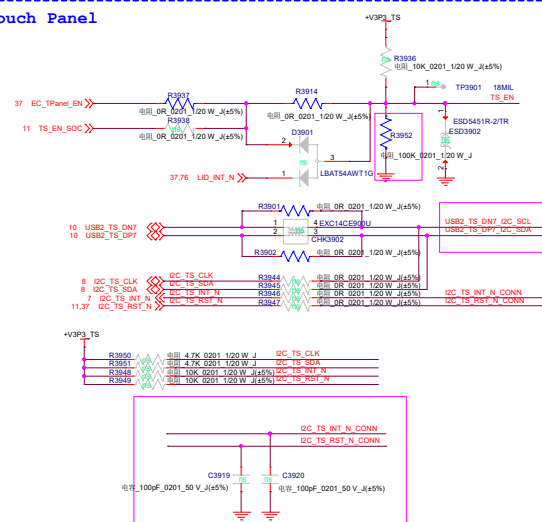
eDP Control



## MIC



Touch Panel



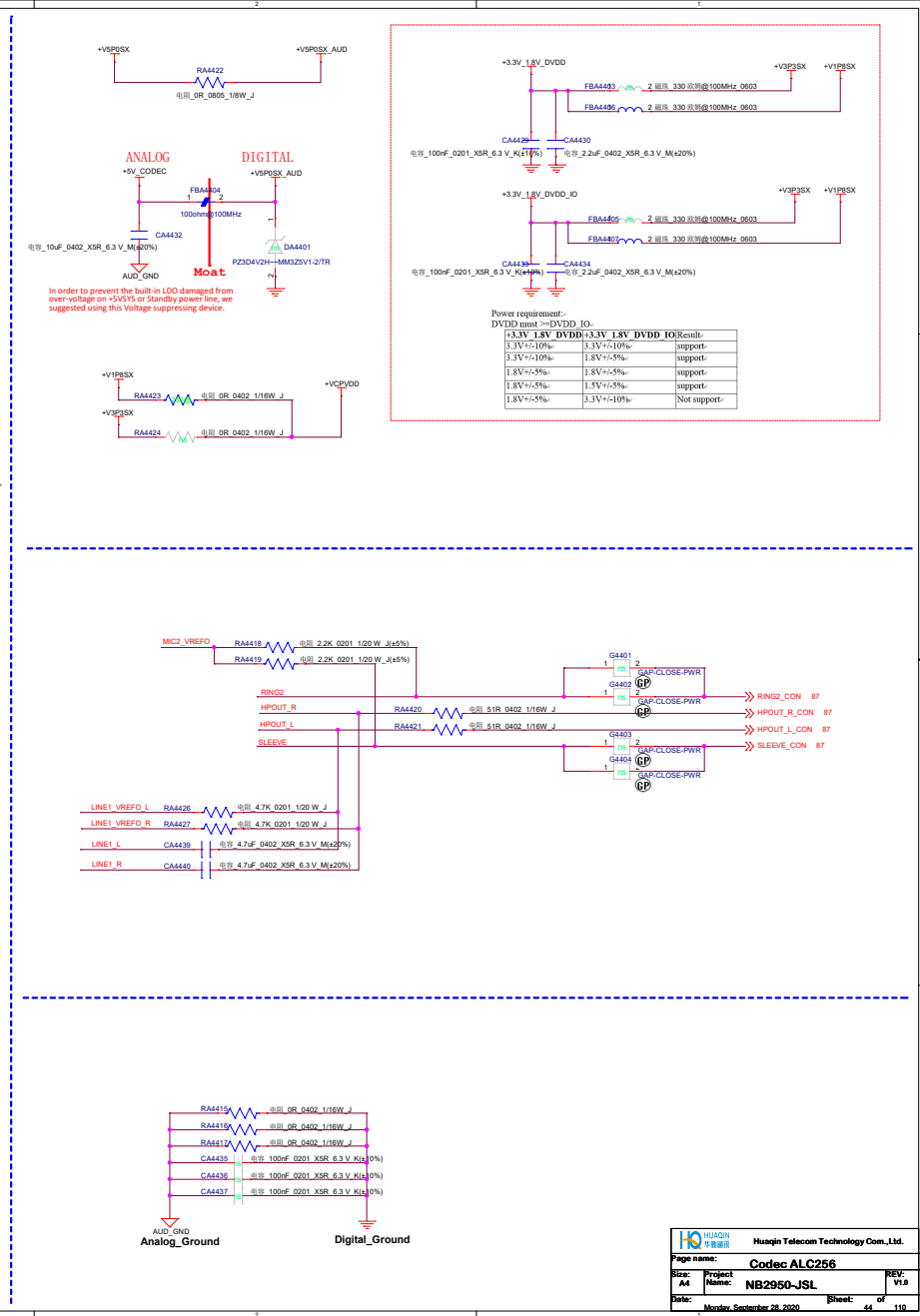
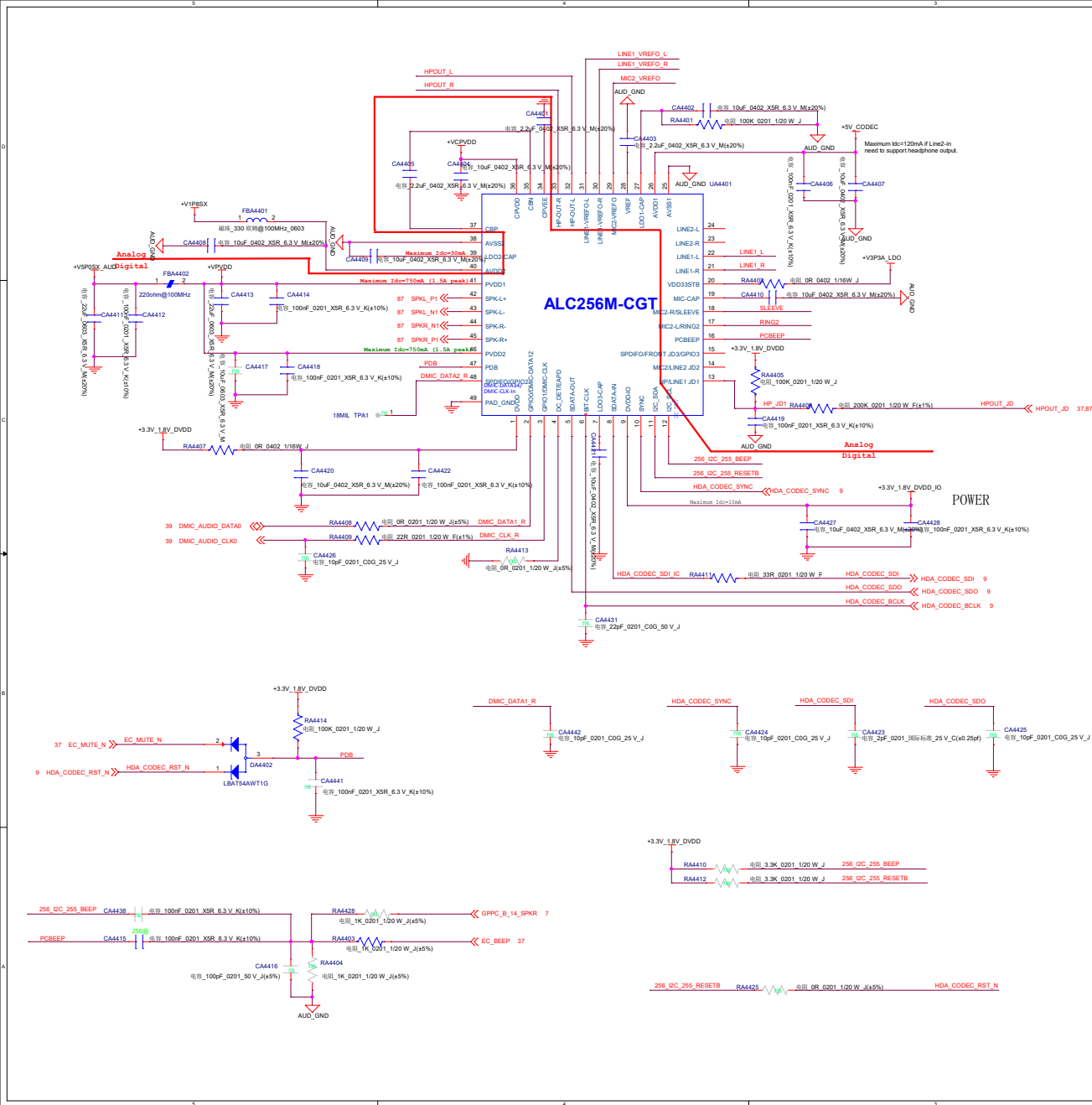








5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1





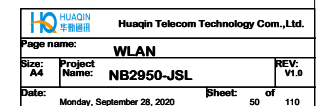


5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1







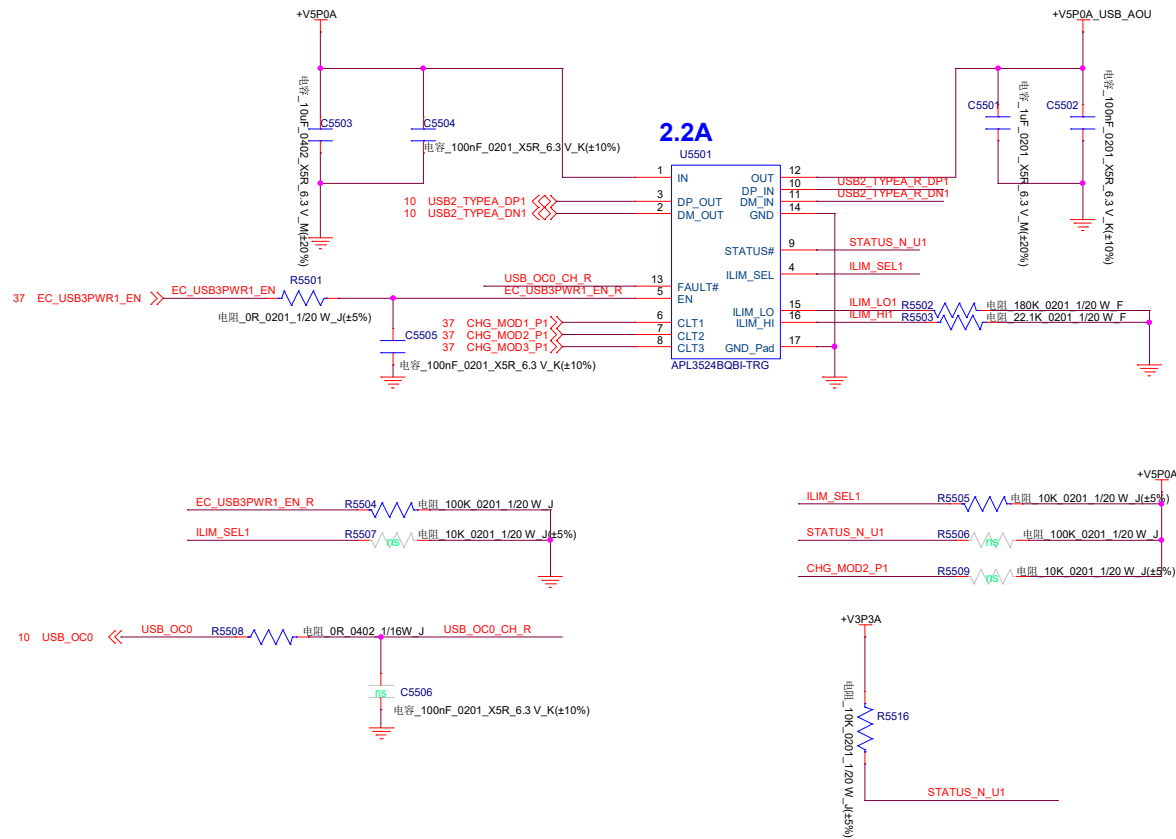
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1



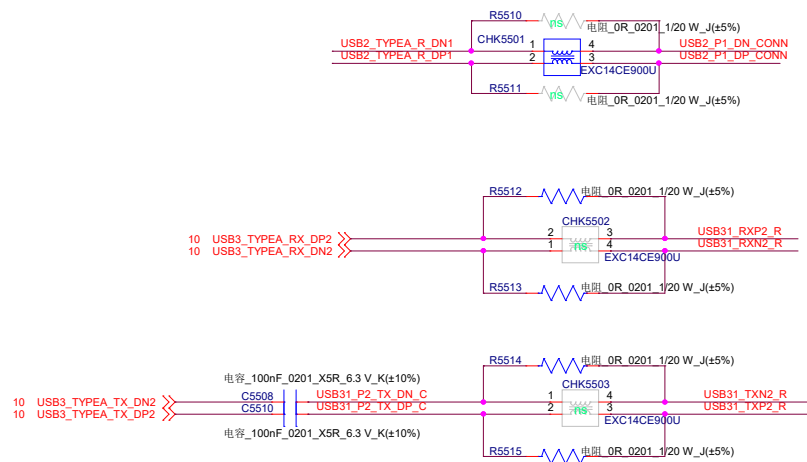




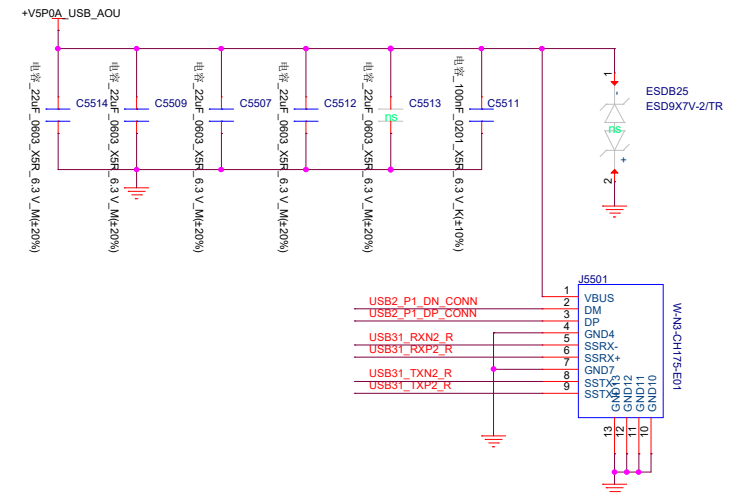
## USB3.1 POWER Port



## USB3.1 Signal



## USB3.1 Connector



## USB3.1 ESD

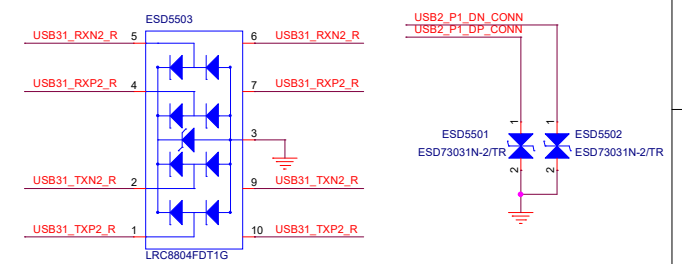
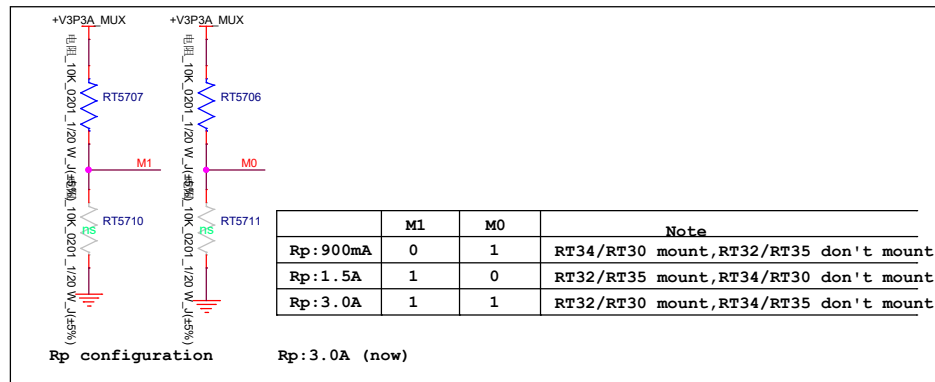
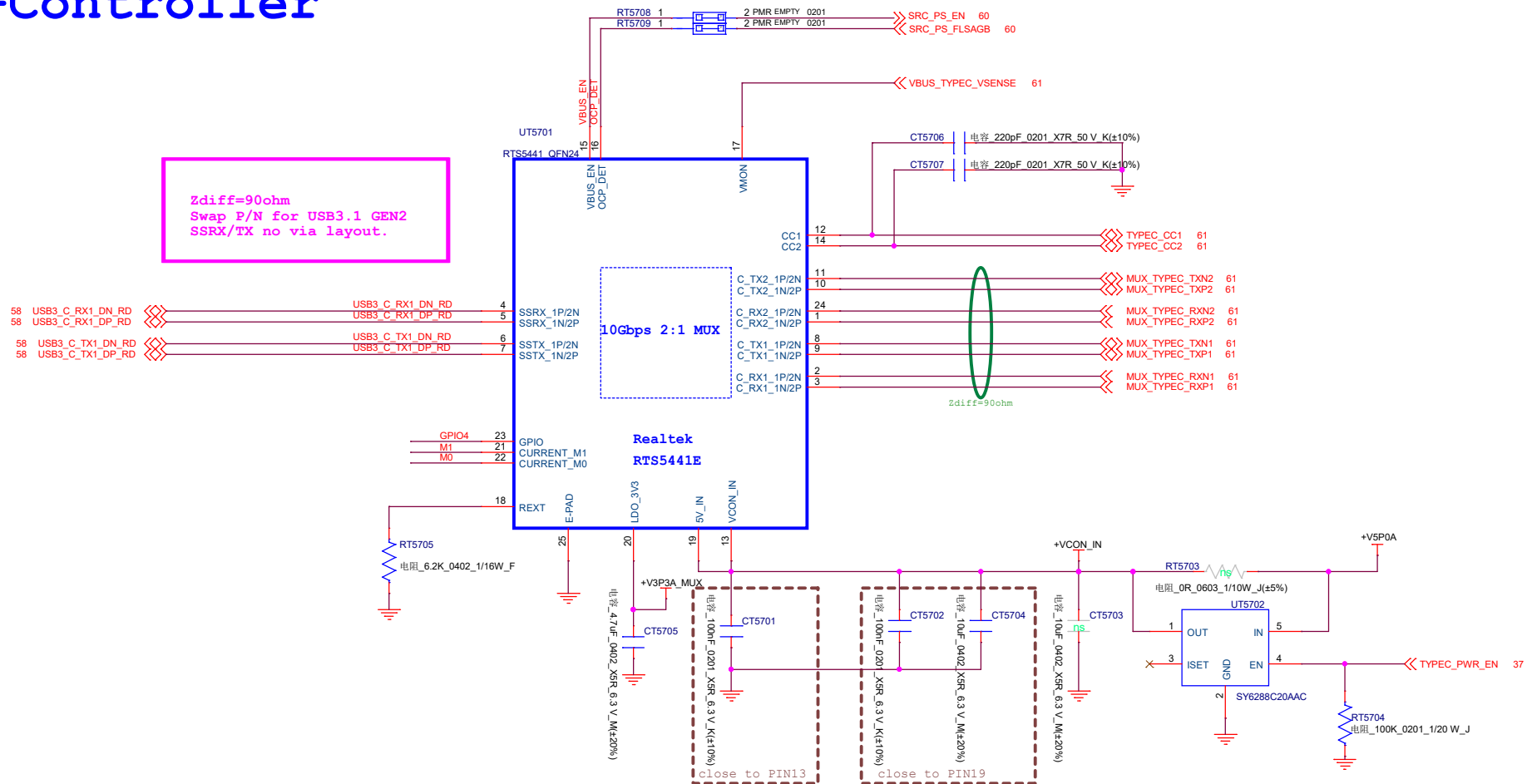


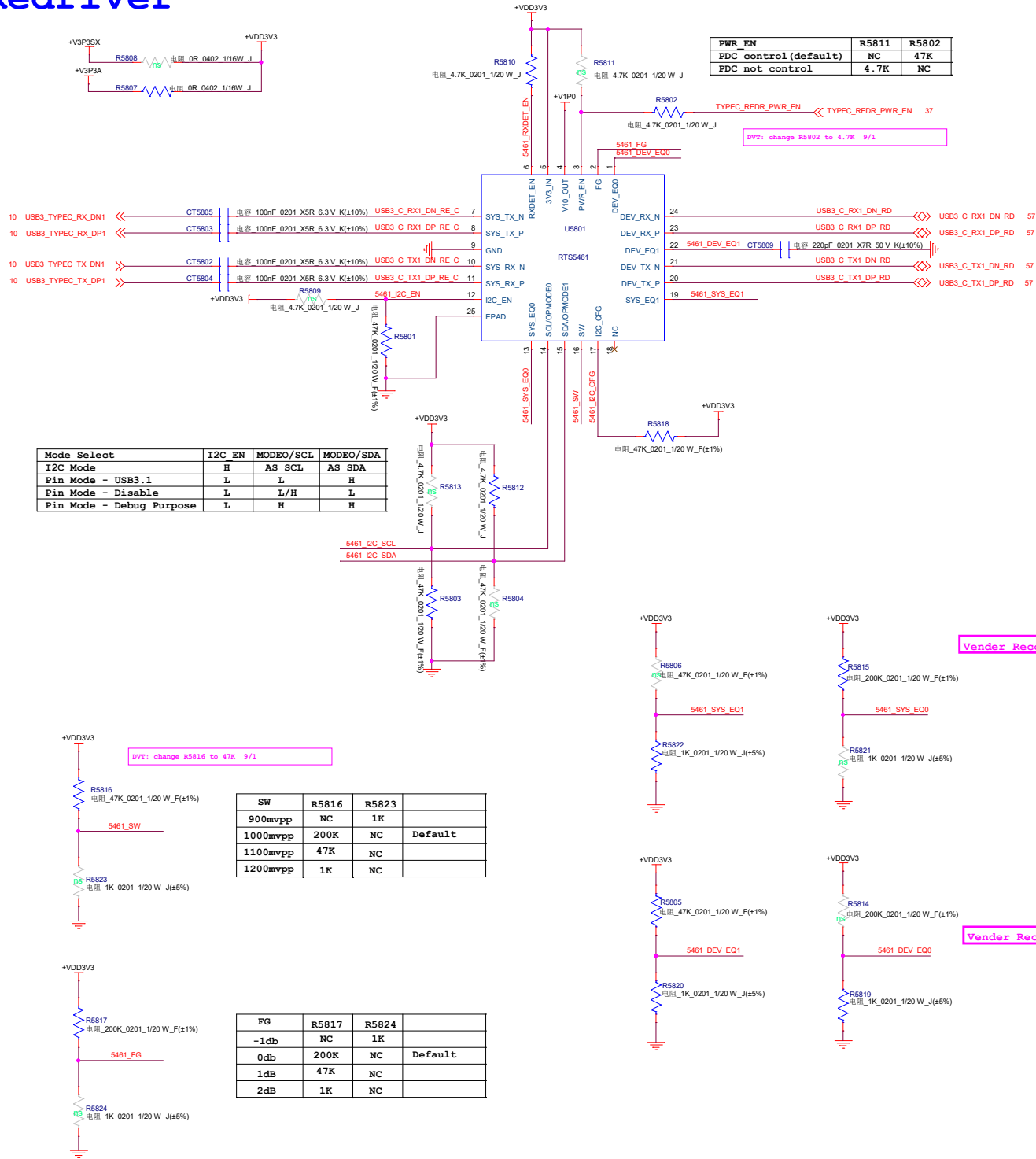




Diagram illustrating the voltage divider circuit for the RT5702 and RT5701 resistors. The circuit is connected to +V3P3A\_MUX and GND. The output of the divider is connected to GPIO4. The resistors are labeled RT5702 and RT5701, both with a value of 10K\_0201\_1/20 W\_J(±5%).



Redriver



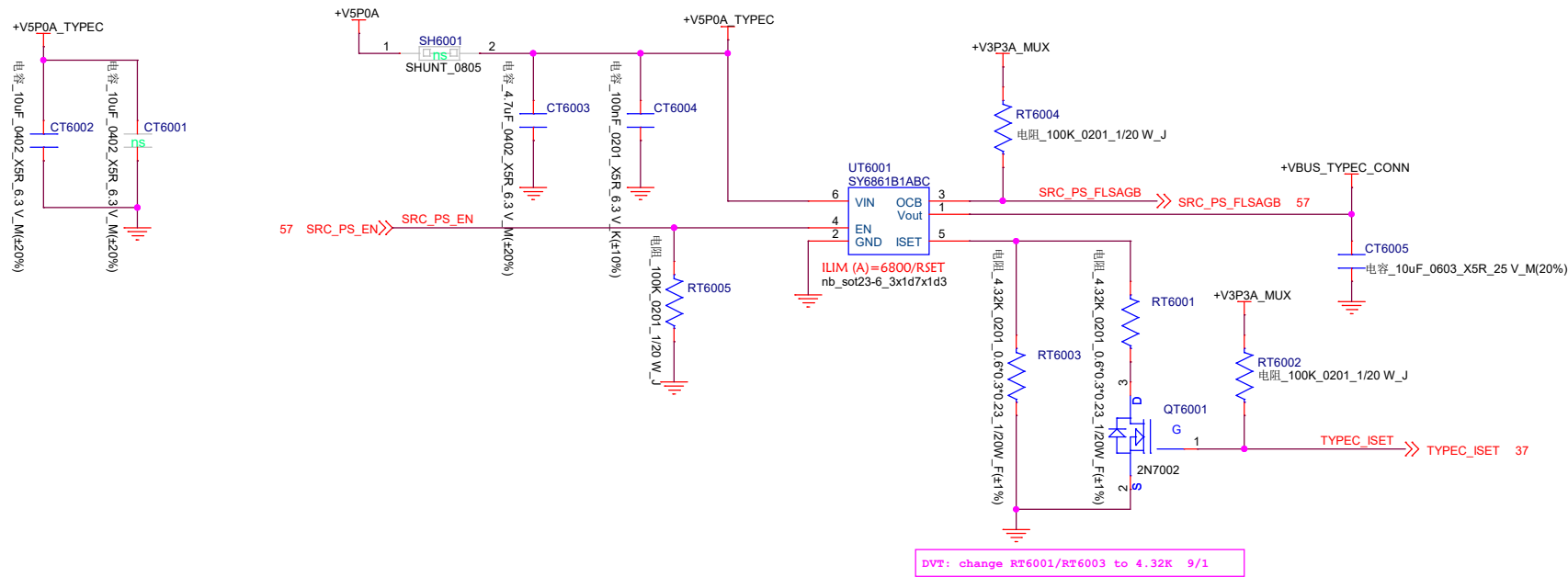
5461_EQX	Rpu	Rpd
L	NC	1K
ML	200K	NC
MH	47K	NC
H	1K	NC

Table 5-3 Host SSTX Channel Equalization Configuration Table				
Host SSTX channel EQ Setting	SYS_EQ1 pin	SYS_EQ0 pin	EQ@2.5GHz (dB)	EQ@5GHz (dB)
0	L	L	-0.3	-0.2
1	L	ML	0.5	1.8
2	L	MH	1.3	3.6
3	L	H	2.2	5.2
4	ML	L	3.2	6.6
5	ML	ML	4.1	7.8
6	ML	MH	5.0	8.9
7	ML	H	5.9	9.8
8	MH	L	6.8	10.3
9	MH	ML	7.6	11.0
10	MH	MH	8.3	11.5
11	MH	H	9.0	12.1
12	H	L	9.7	12.4
13	H	ML	10.3	12.9
14	H	MH	10.9	13.2
15	H	H	11.4	13.6

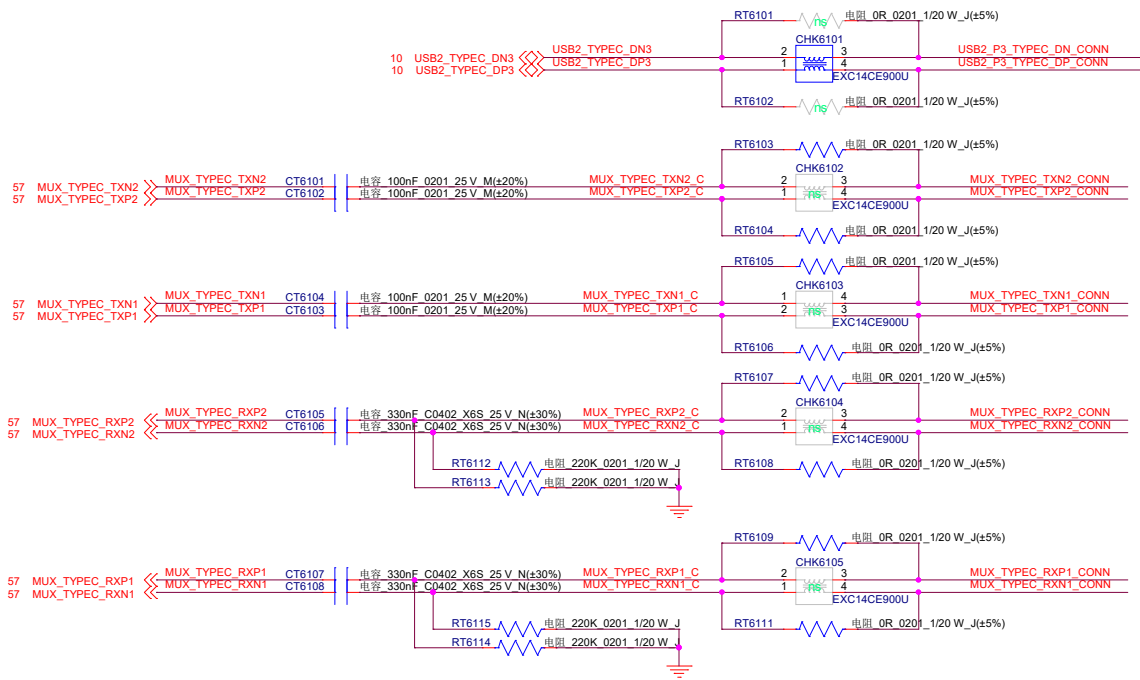
Table 5-4 Host SSRX Channel Equalization Configuration Table				
Host SSRX channel EQ Setting	DEV_EQ1 pin	DEV_EQ0 pin	EQ@2.5GHz (dB)	EQ@5GHz (dB)
0	L	L	-0.3	-0.2
1	L	ML	0.5	1.8
2	L	MH	1.3	3.6
3	L	H	2.2	5.2
4	ML	L	3.2	6.6
5	ML	ML	4.1	7.8
6	ML	MH	5.0	8.9
7	ML	H	5.9	9.8
8	MH	L	6.8	10.3
9	MH	ML	7.6	11.0
10	MH	MH	8.3	11.5
11	MH	H	9.0	12.1
12	H	L	9.7	12.4
13	H	ML	10.3	12.9
14	H	MH	10.9	13.2
15	H	H	11.4	13.6



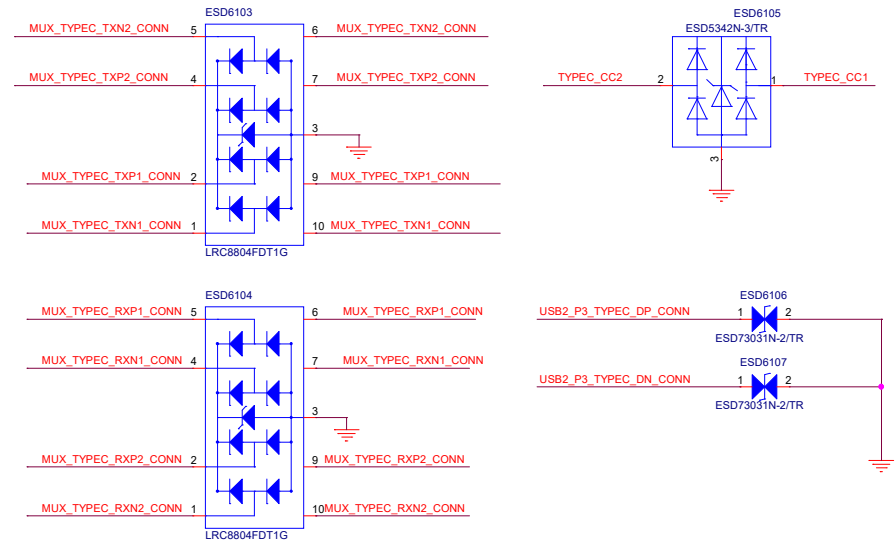
## TYPEC Output



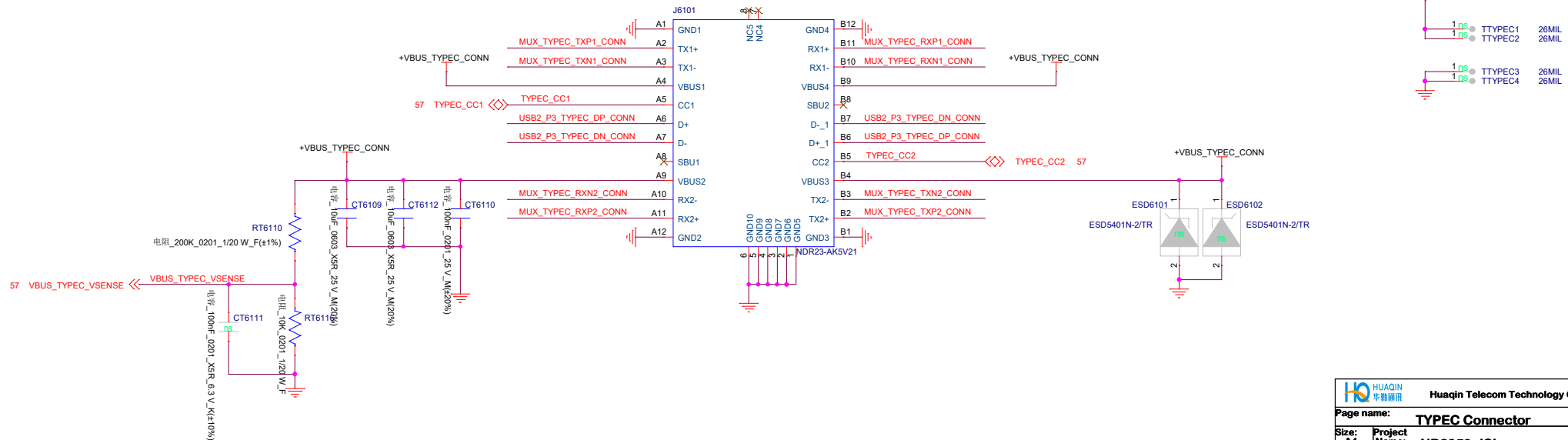
## TYPE-C Signal



## TYPE-C ESD



## TYPE-C Connector



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1







	5	4	3	2	1
D					
C					
B					
A					



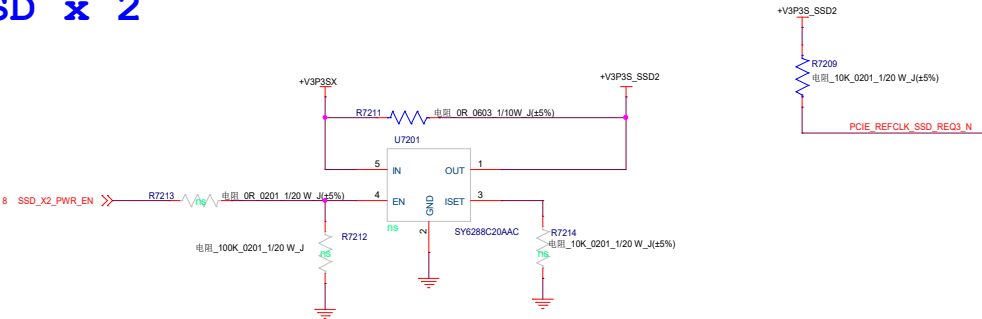




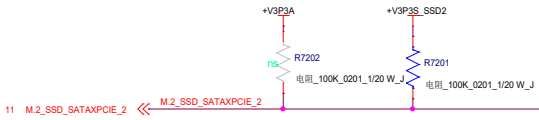
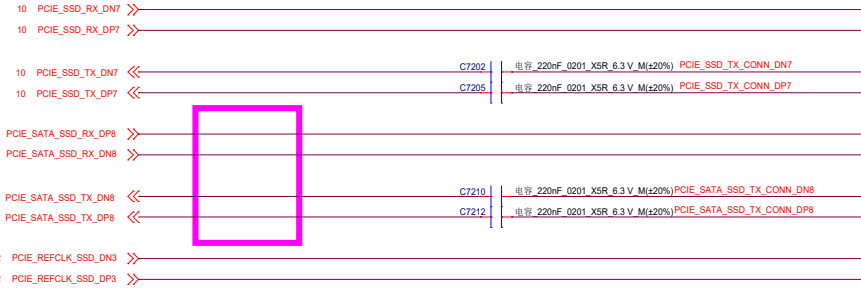




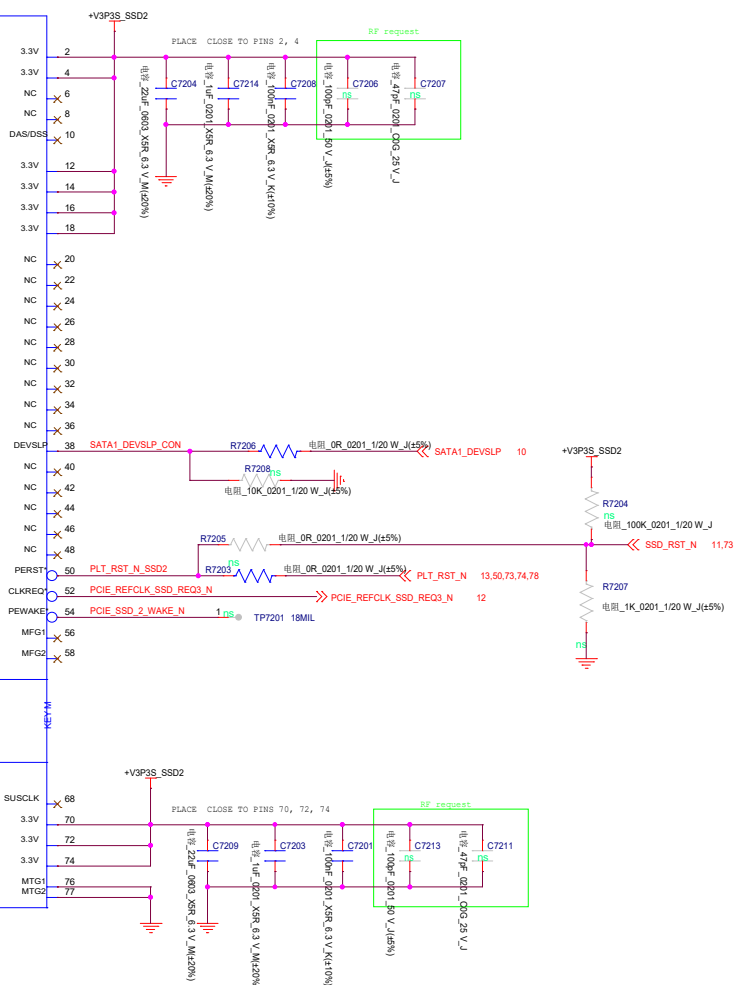
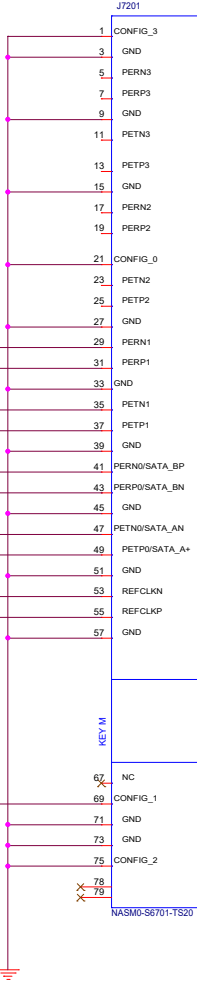
SSD x 2



PCIE3.0 X2 & SATA3.0 X1

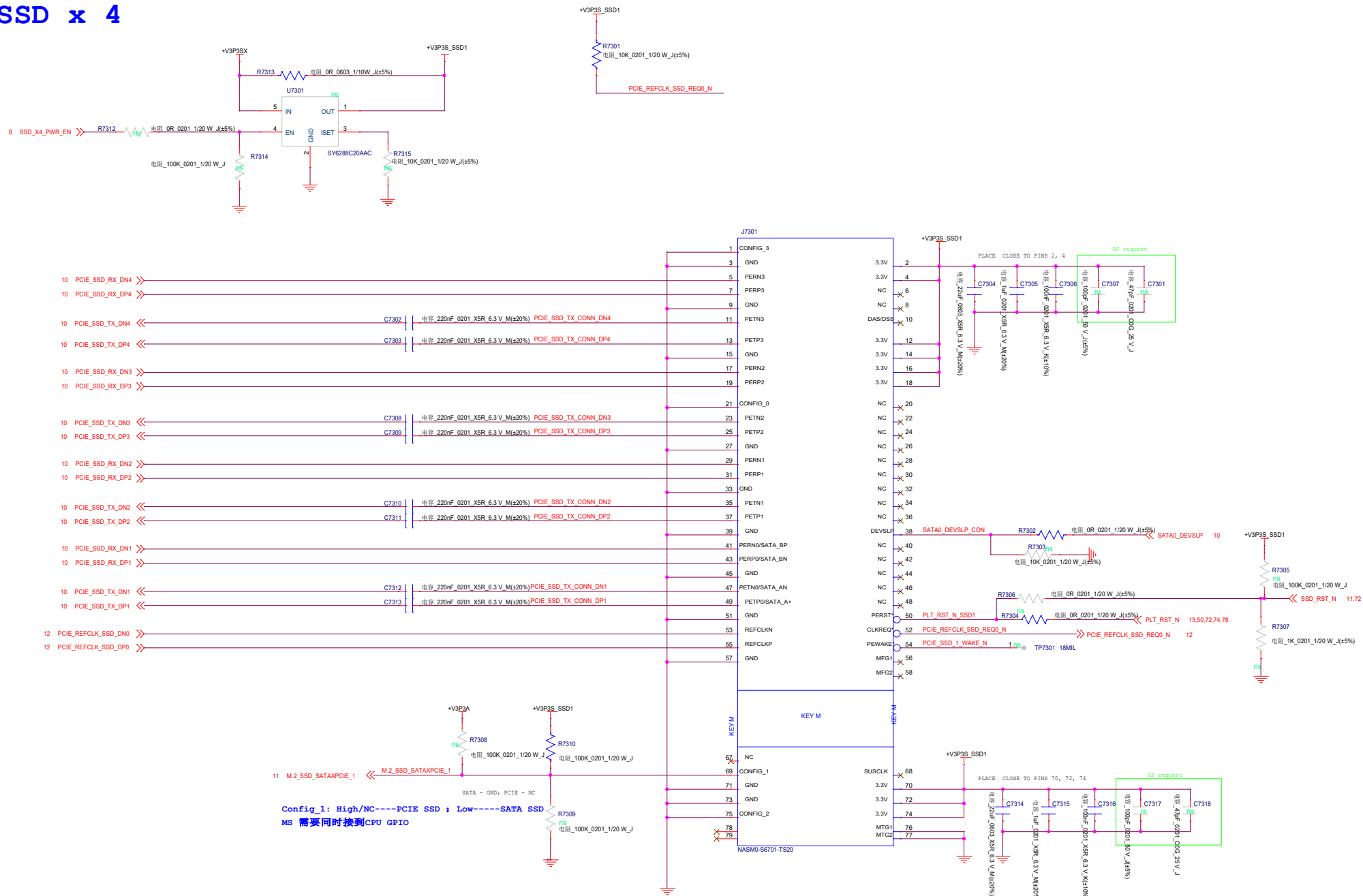


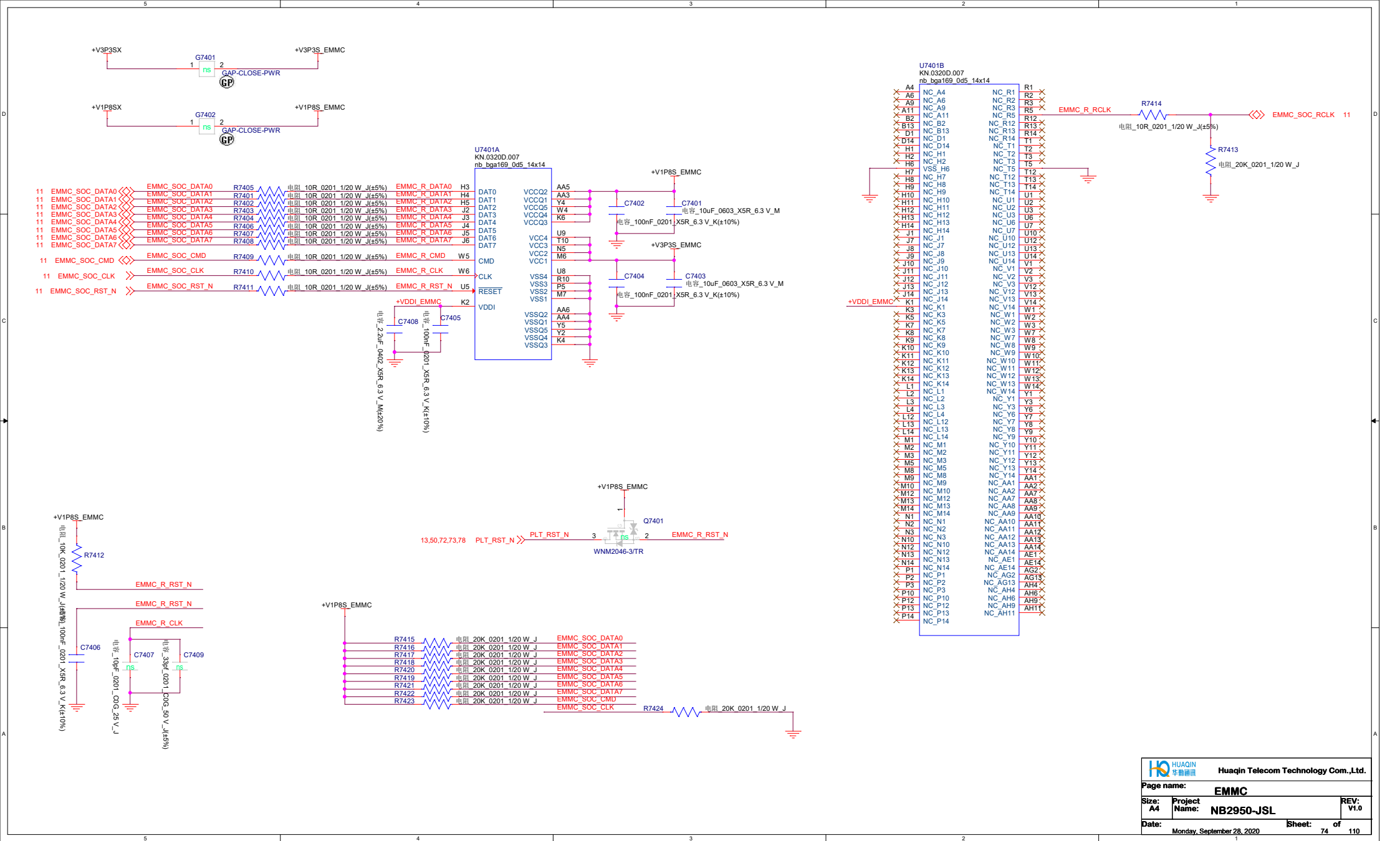
Config 1: High/NC---PCIE SSD only  
MS 需要同时接到CPU GPIO





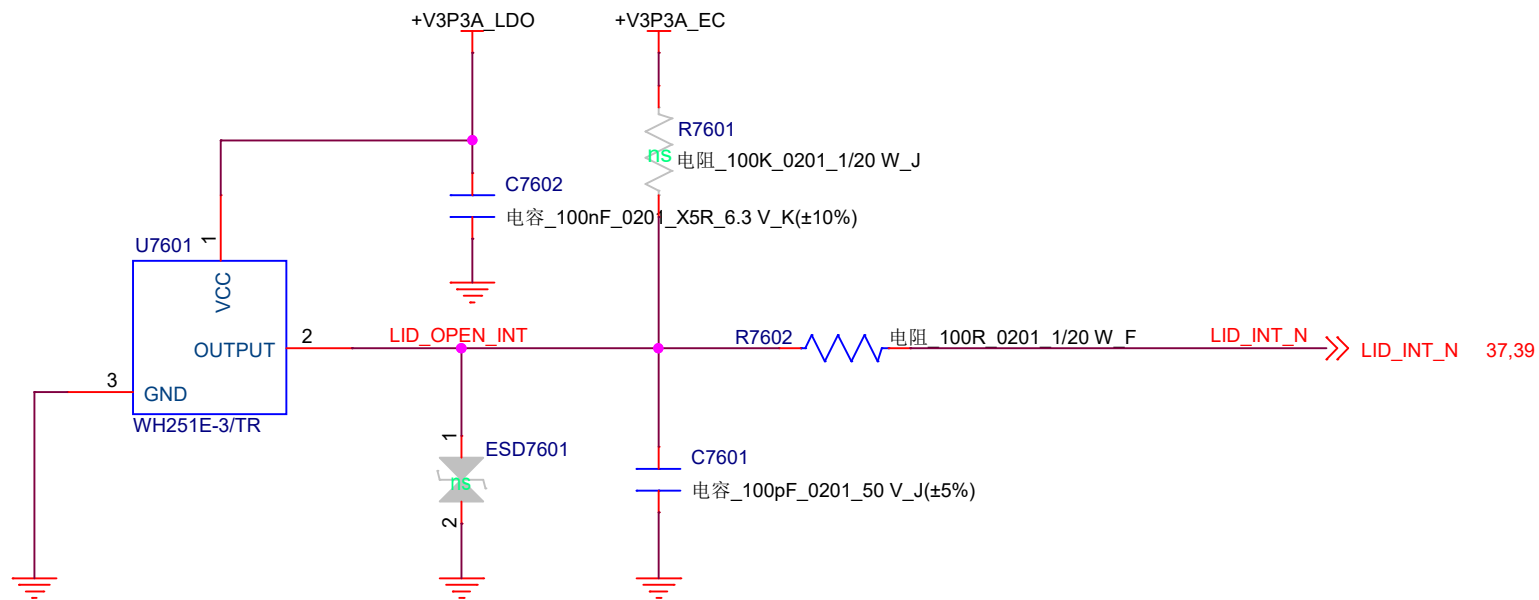
## SSD x 4



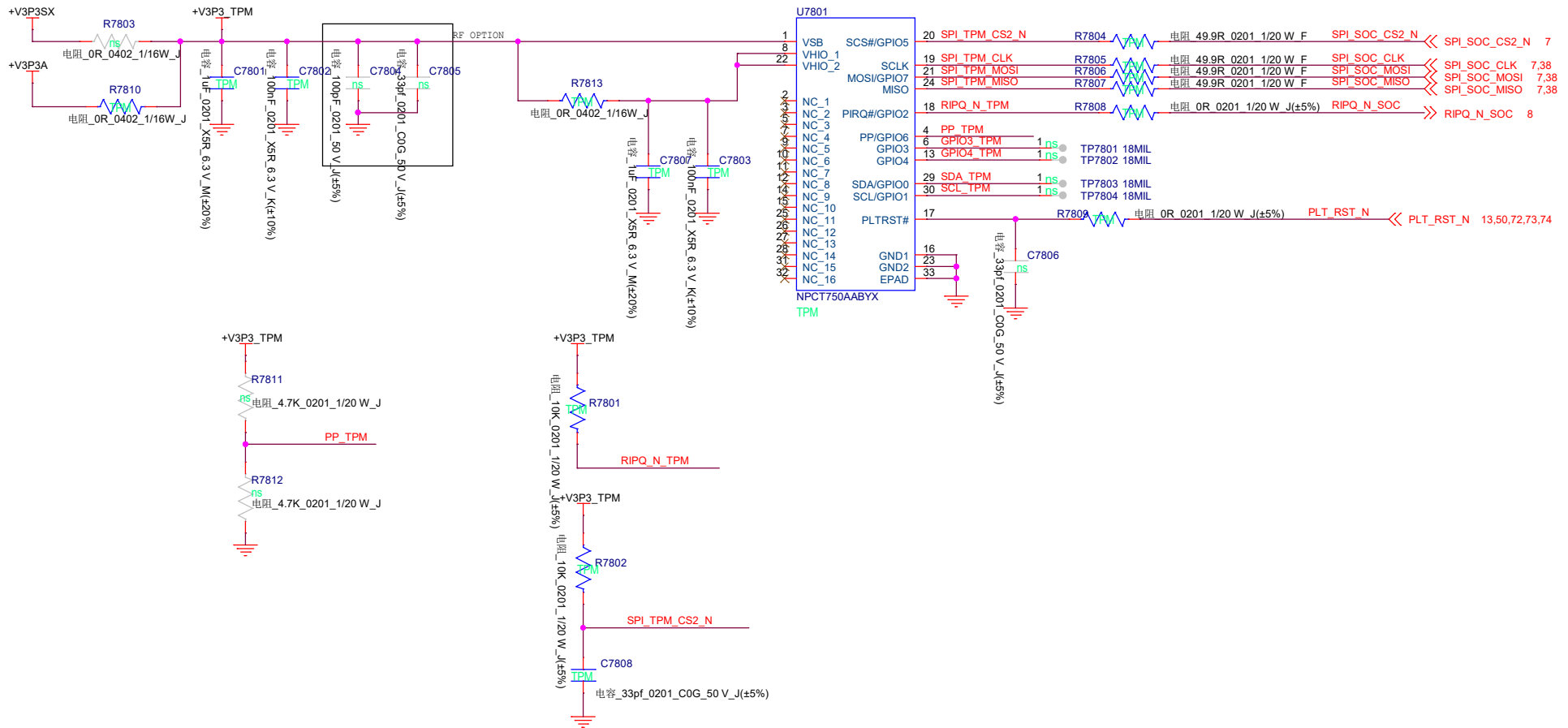


5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

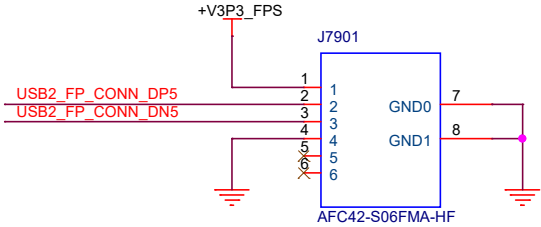
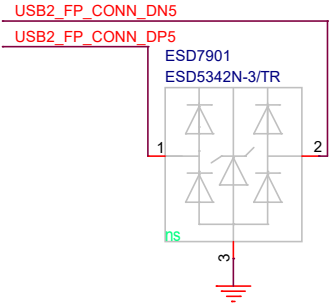
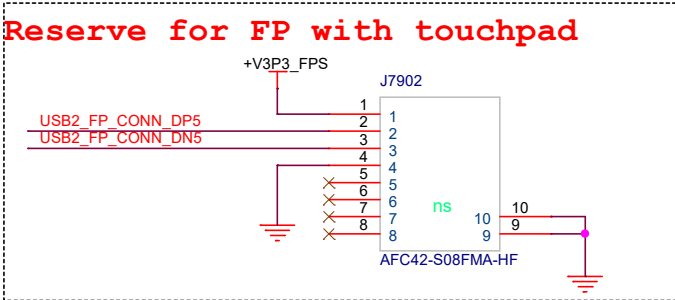
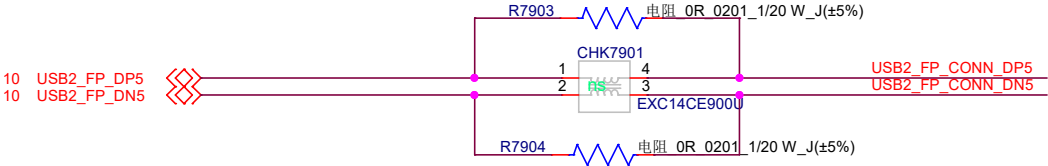
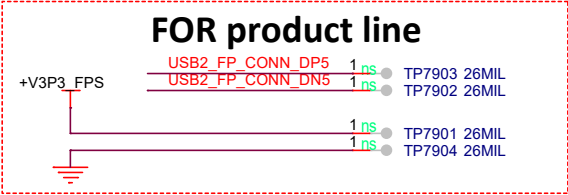
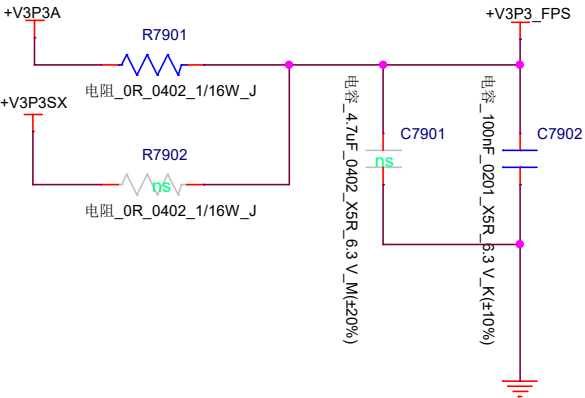
# HALL



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1



# Finger Print

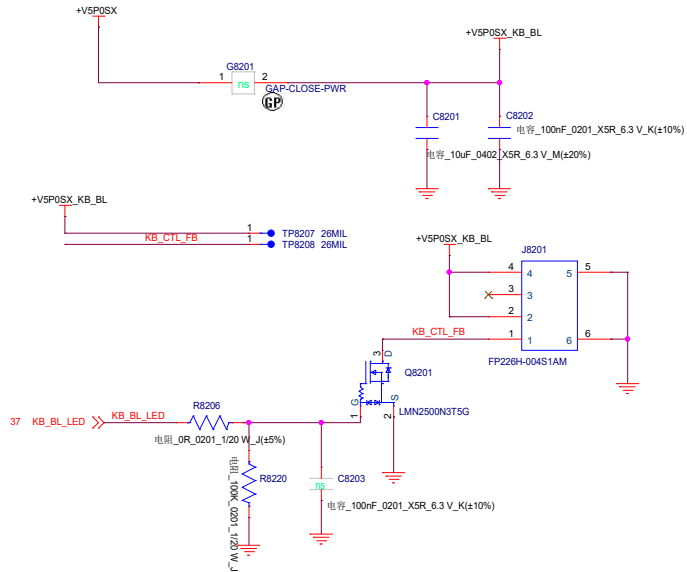






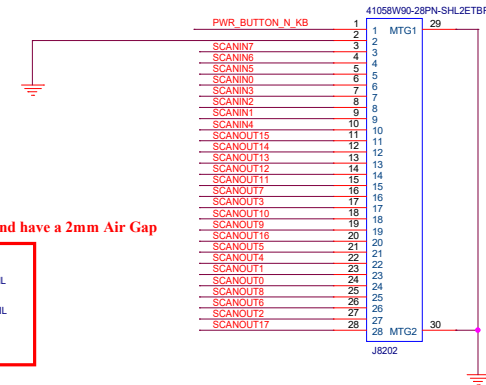
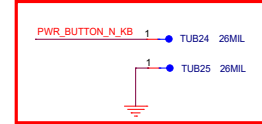
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

## KB Backlight

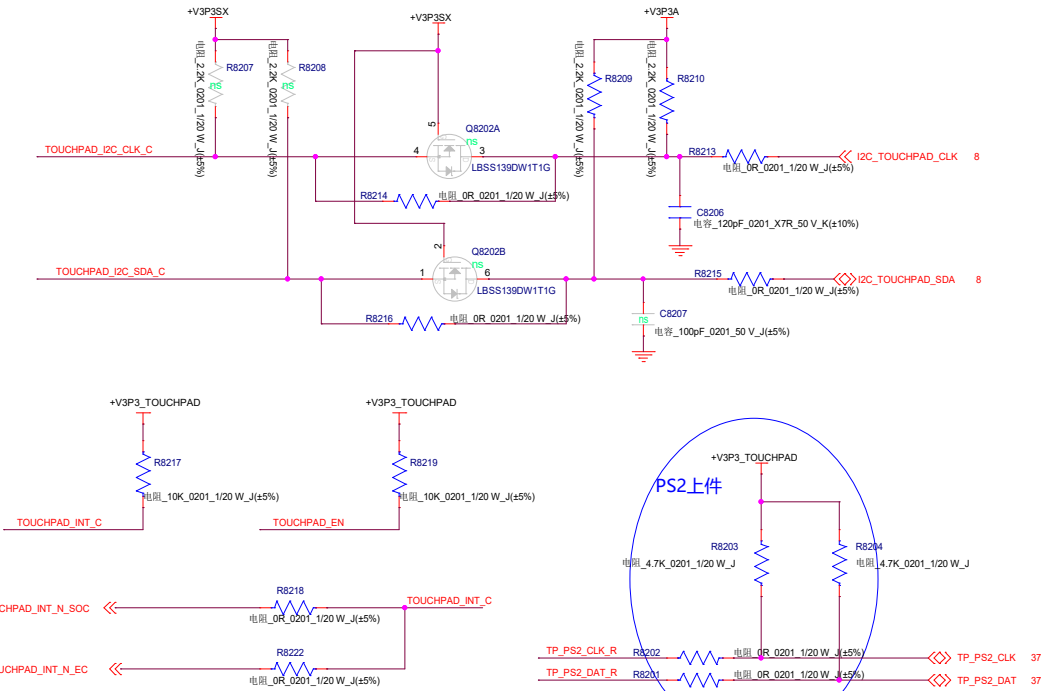


## KB CONN

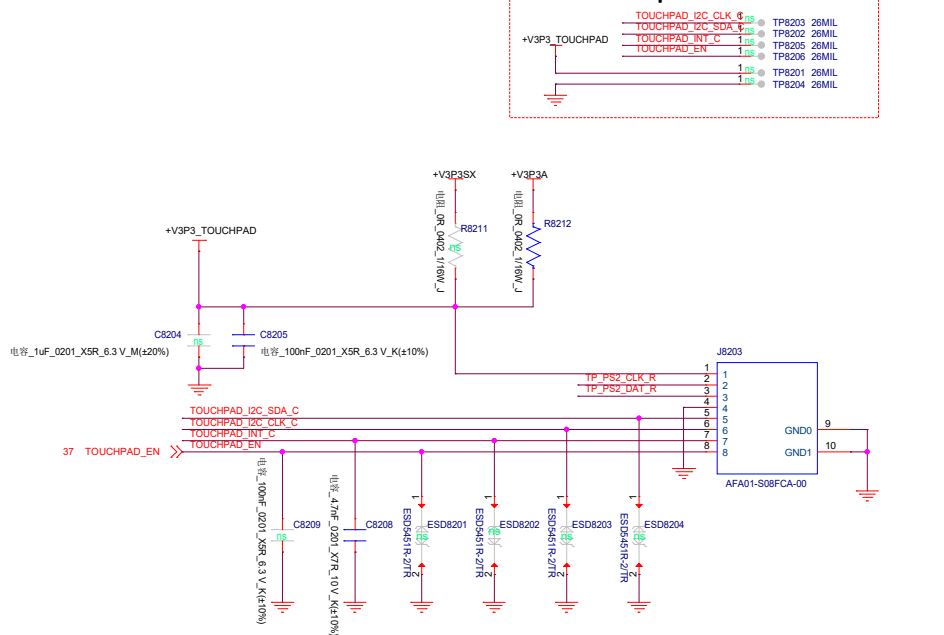
2 Test Point place on Bottom Lay and have a 2mm Air Gap



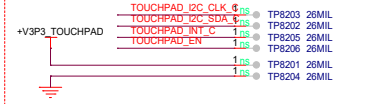
## Touch Pad



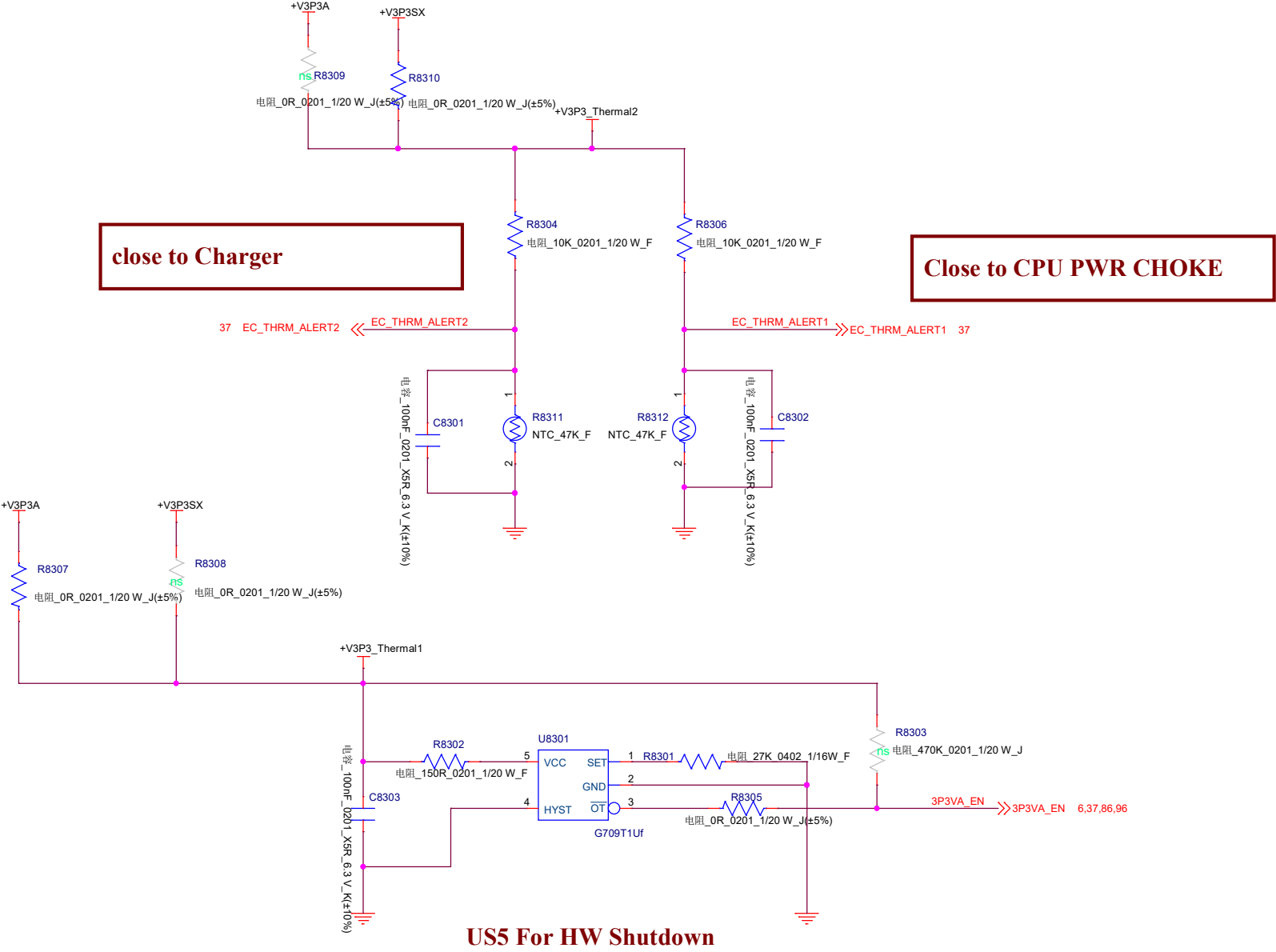
## Touch Pad CONN




FOR product line



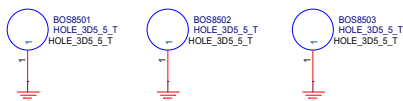
REMOTE1+/-, Trace width/space:10/10 mil,Trace length:<8"  
Connect guard traces to GND on either side of the  
DXP-DXN traces



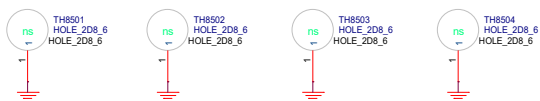
		Huaqin Telecom Technology Com.,Ltd.	
Page name: Thermal sensor			
Size: A4	Project Name: NB2950-JSL	REV: V1.0	
Date: Monday, September 28, 2020	Sheet: 83	of 110	



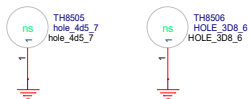
## Thermal Pad BOSS \*3



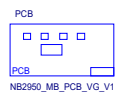
## HOLE \*4



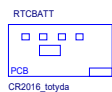
## HOLE \*2



## PCB



## RTC

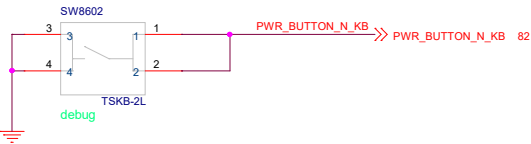


Reset BUTTON

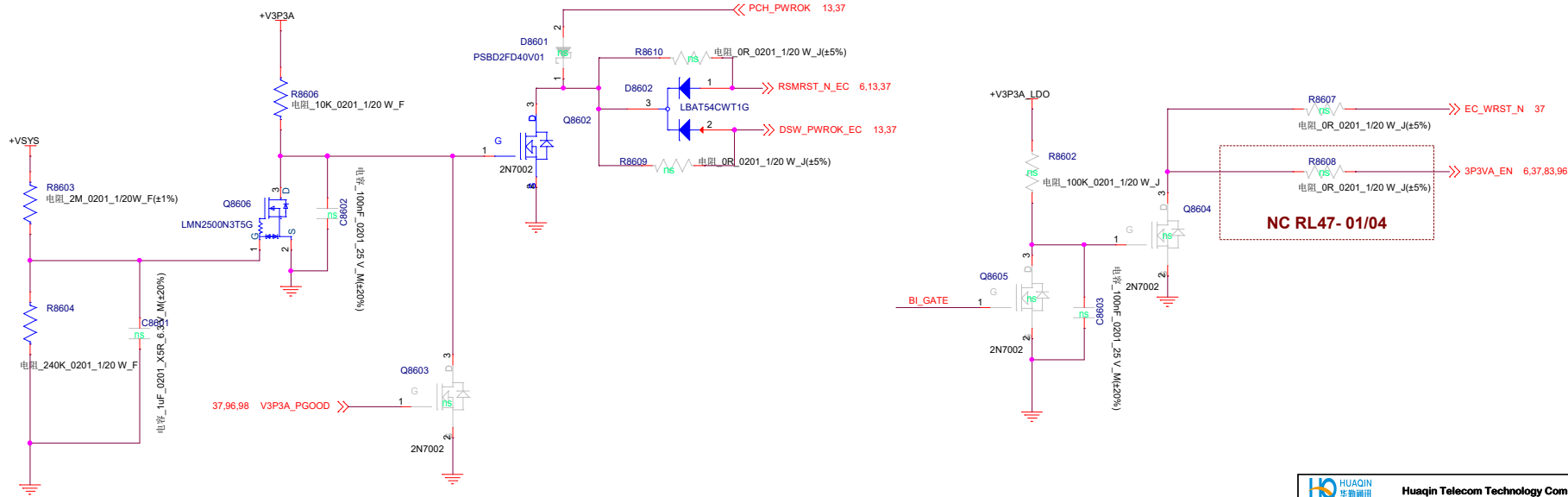


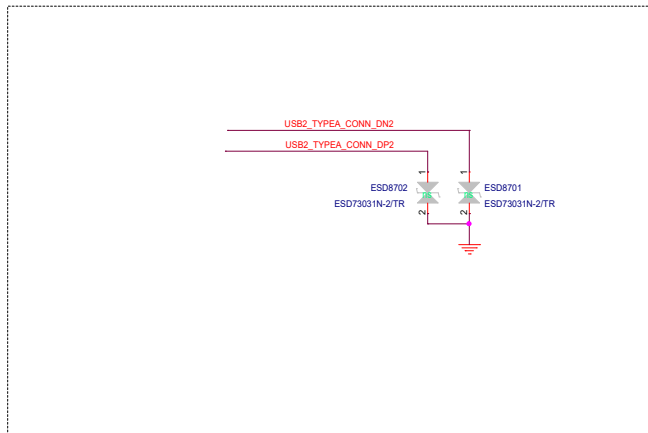
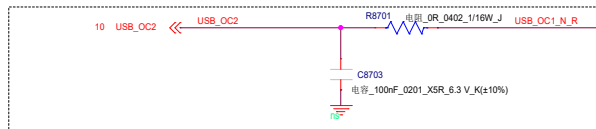
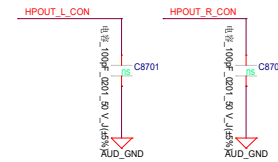
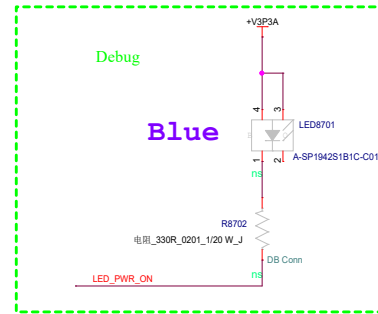
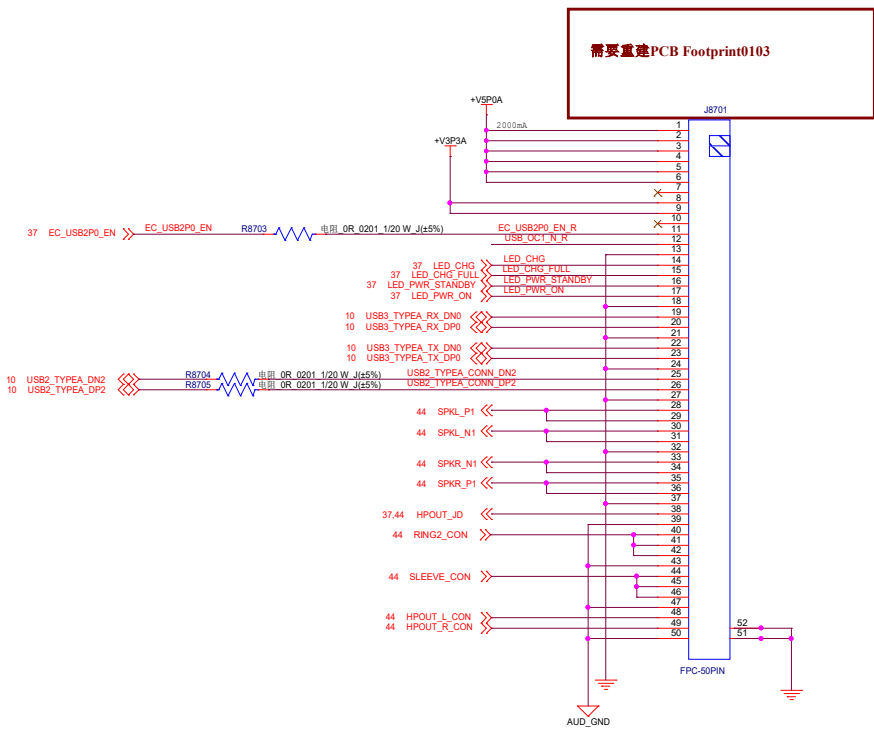
Open door BUTTON

Debug BUTTON

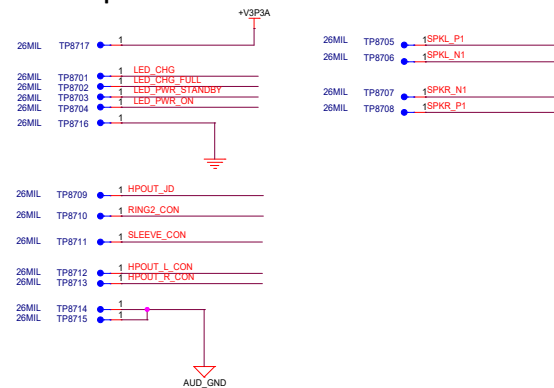


Abnormal PD logic

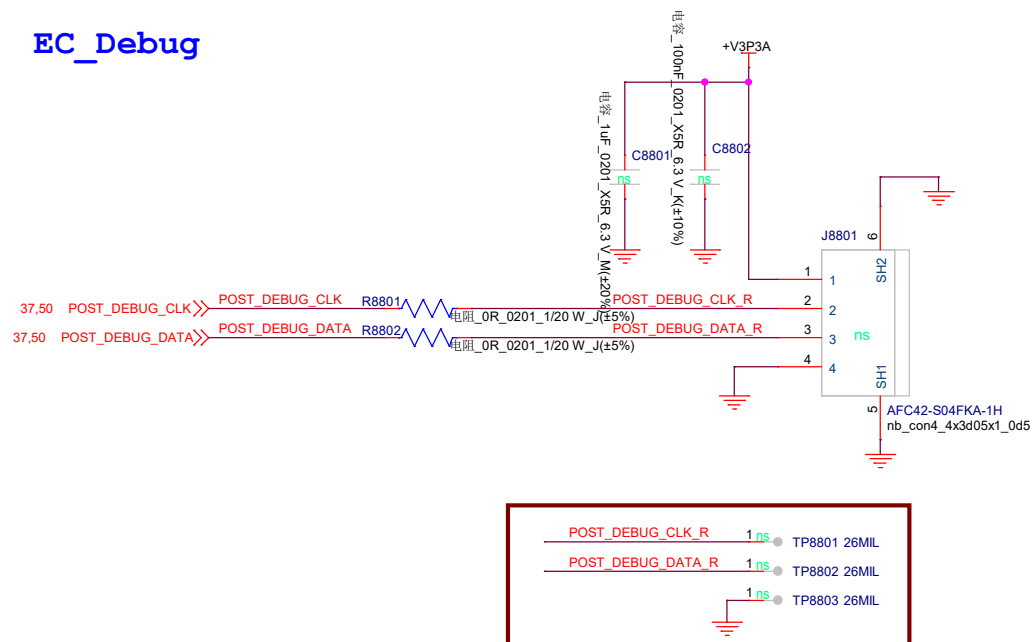




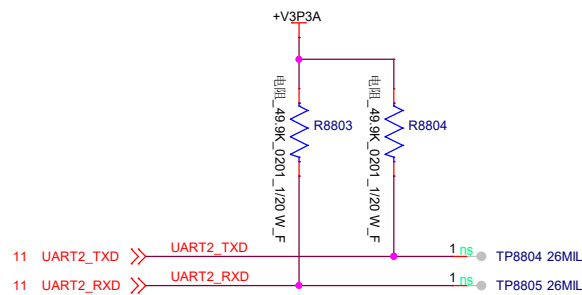
## FOR product line



## EC\_Debug



## System\_UART\_Debug







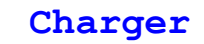




5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

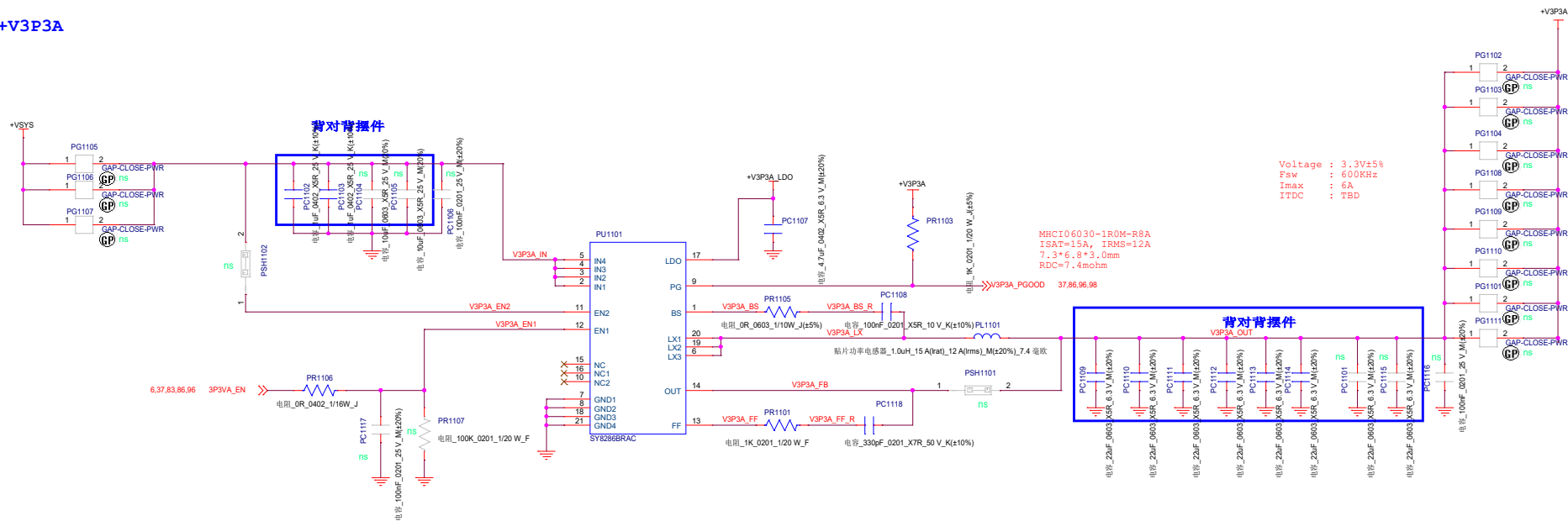
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1



3P3VA\_EN 6.37,83,96,96  
V3P3A\_PG00D 37,86,96,98

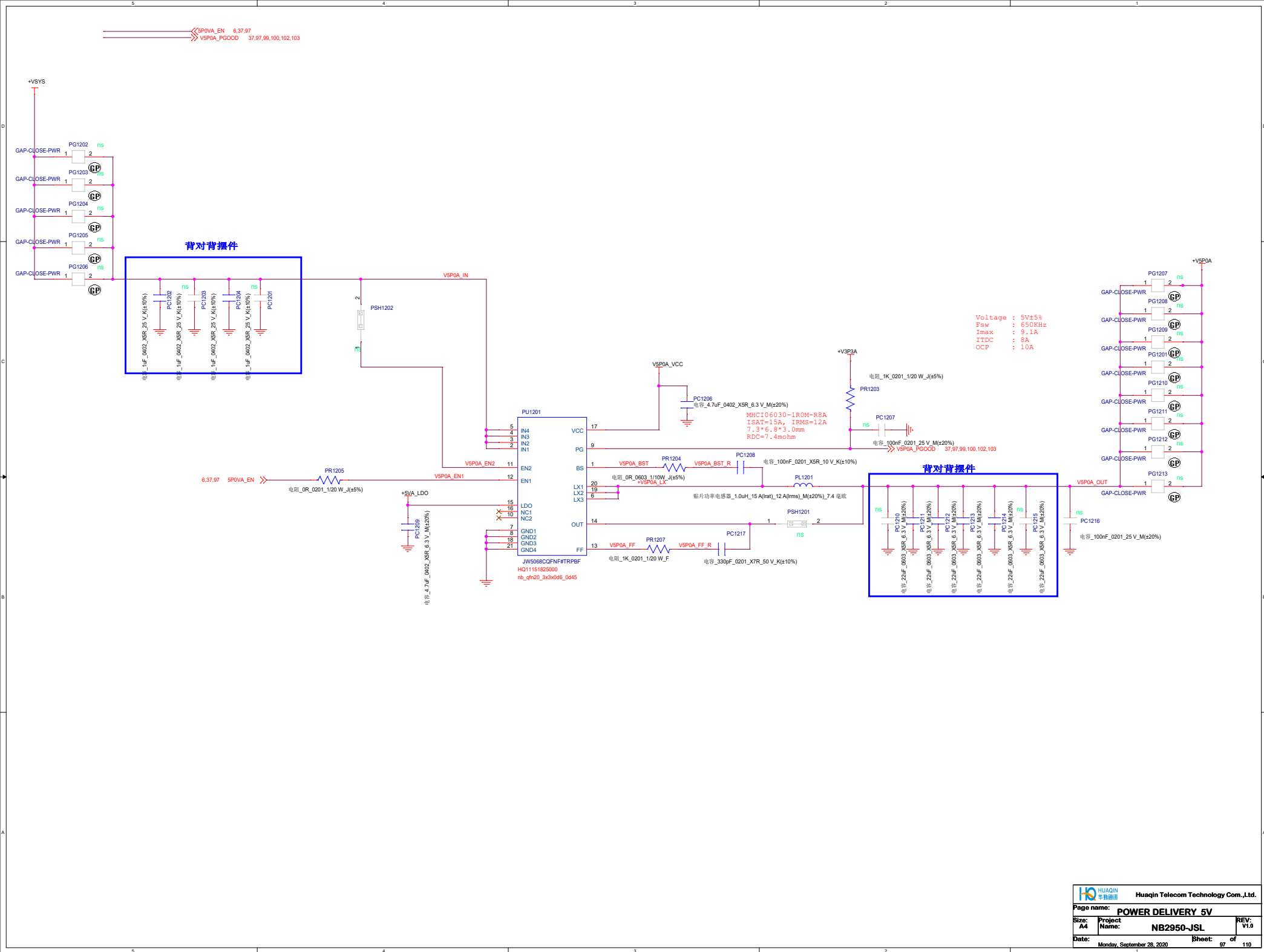
## +V3P3A

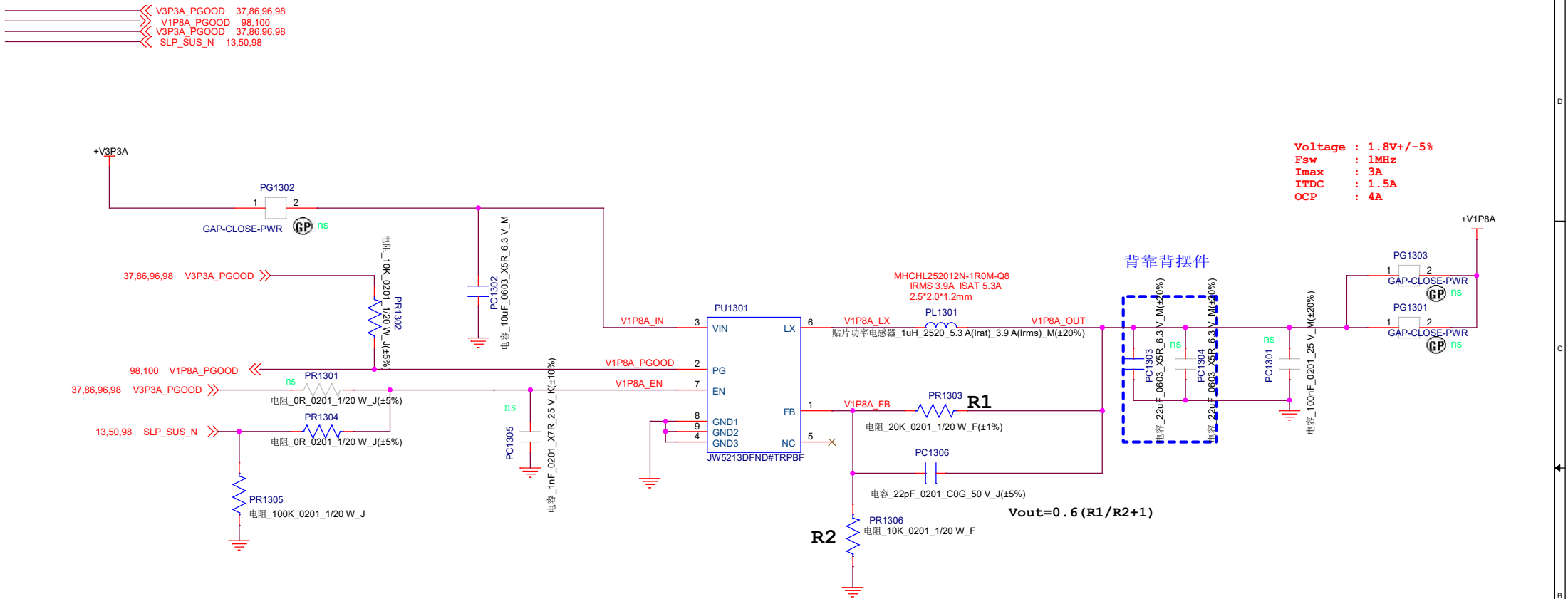


Voltage : 3.3V±5%  
Fsw : 600KHz  
Imax : 6A  
ITDC : TBD

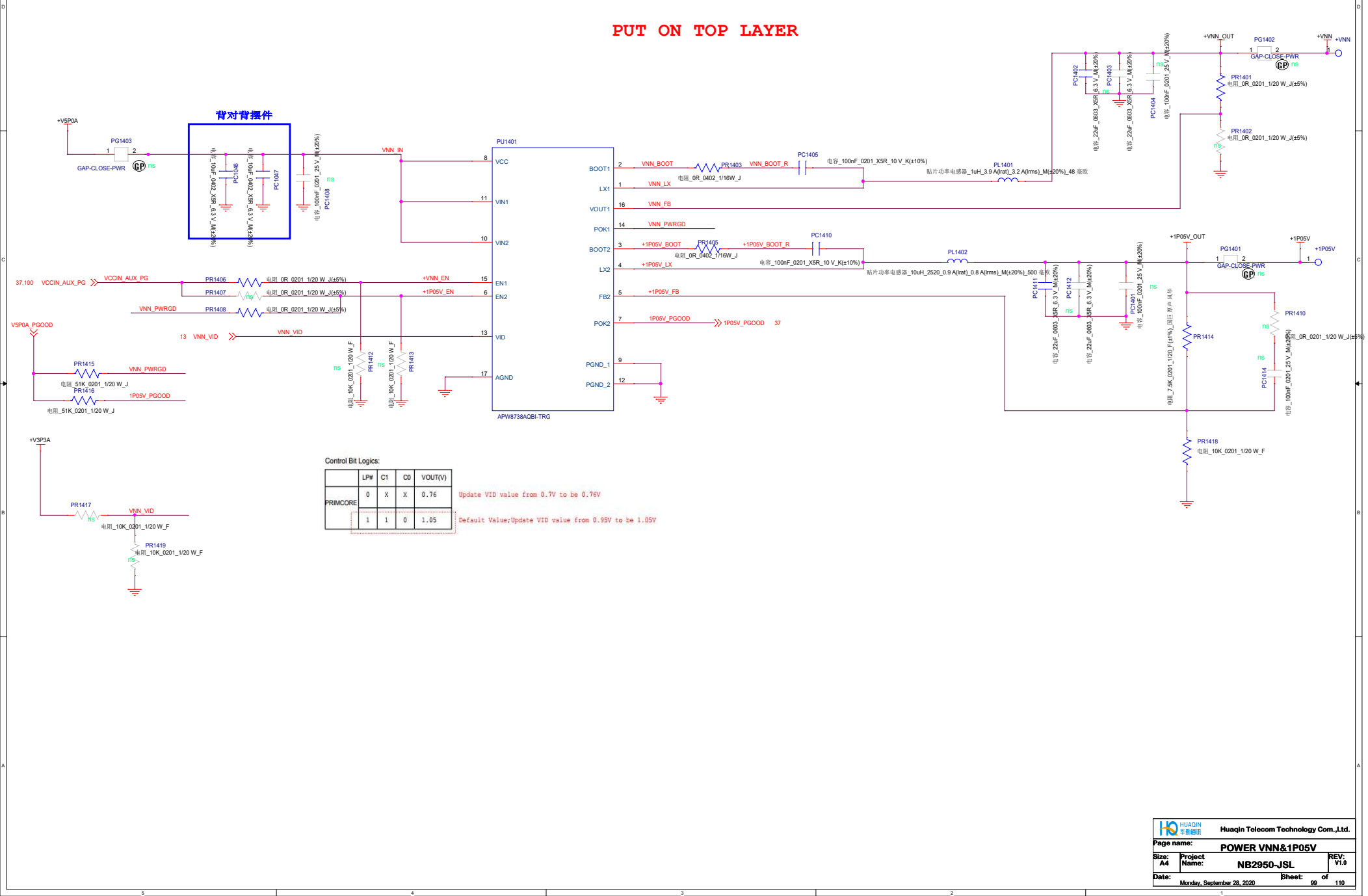
MHCI06030-1R0M-R8A  
ISAT=15A, IRMS=12A  
7.3\*6.8\*3.0mm  
RDC=1.4mohm

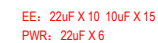






PUT ON TOP LAYER

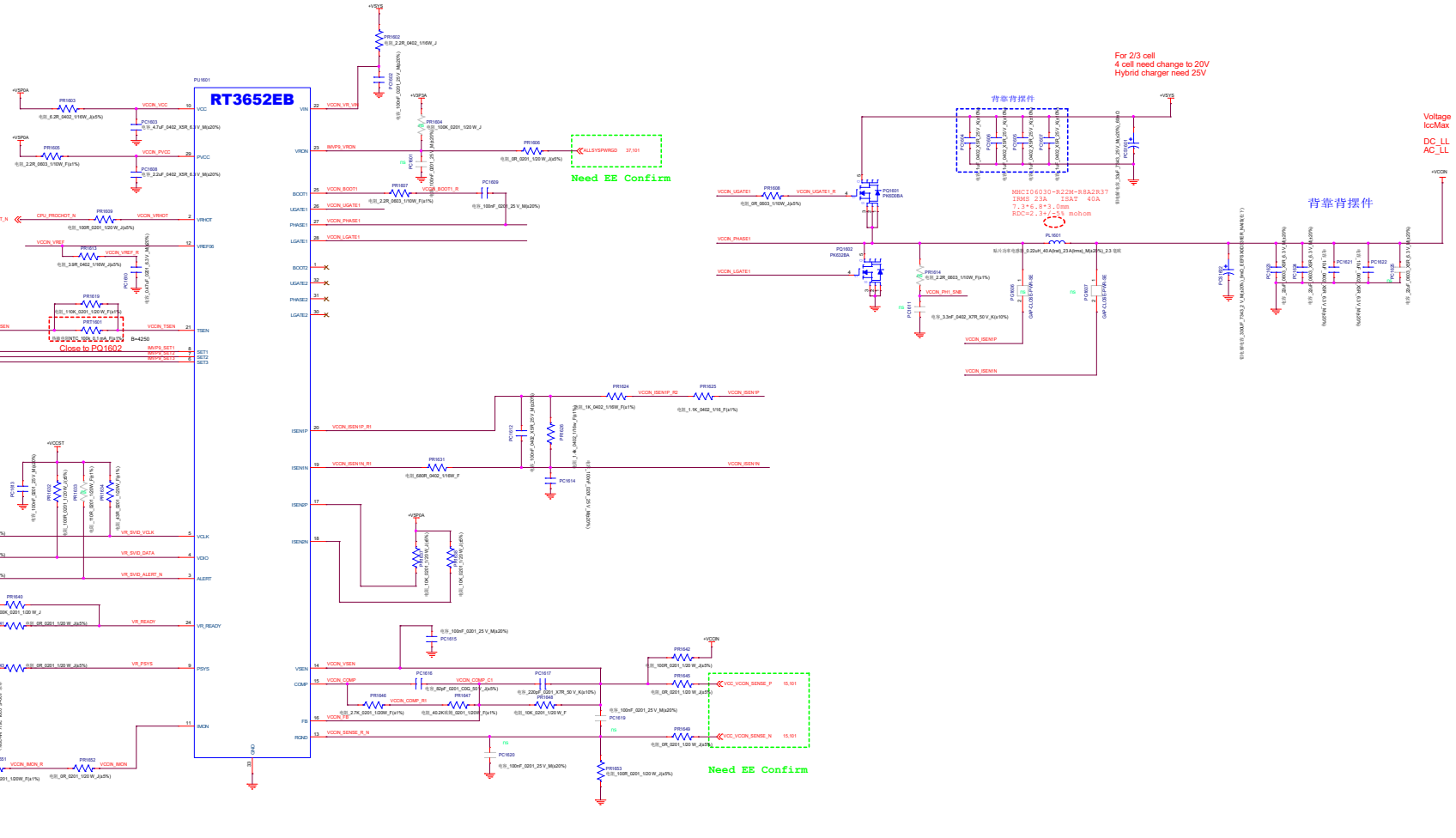




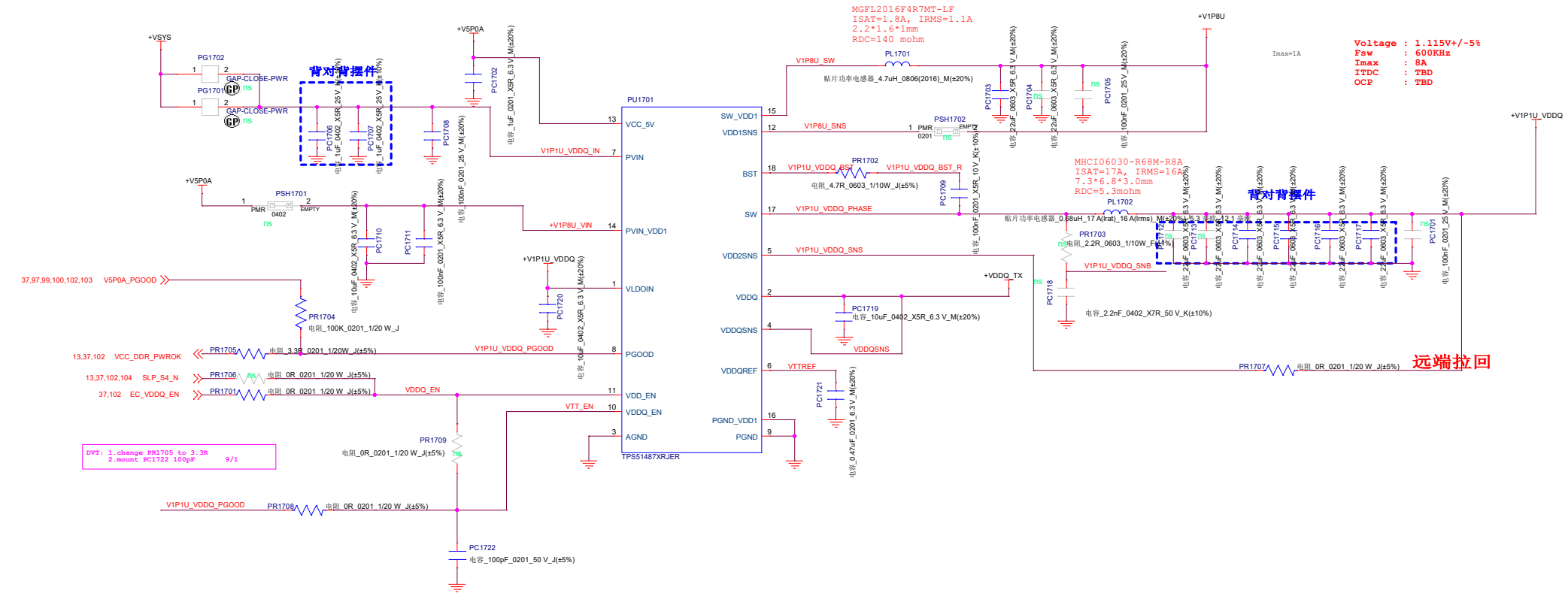
ALLSYSWROD 37.01  
 CPU\_PWDEN1\_N 0.1137.001  
 VCON\_VCONN 0.101  
 VCON\_VCONP 0.101  
 VCON\_VCONN\_N 0.101  
 VCON\_VCONN\_P 0.101  
 VCON\_VCONN\_S 0.101  
 VCON\_VCONN\_S\_N 0.101  
 VCON\_VCONN\_S\_P 0.101

Number of Gaps Depend on Battery cells and placement

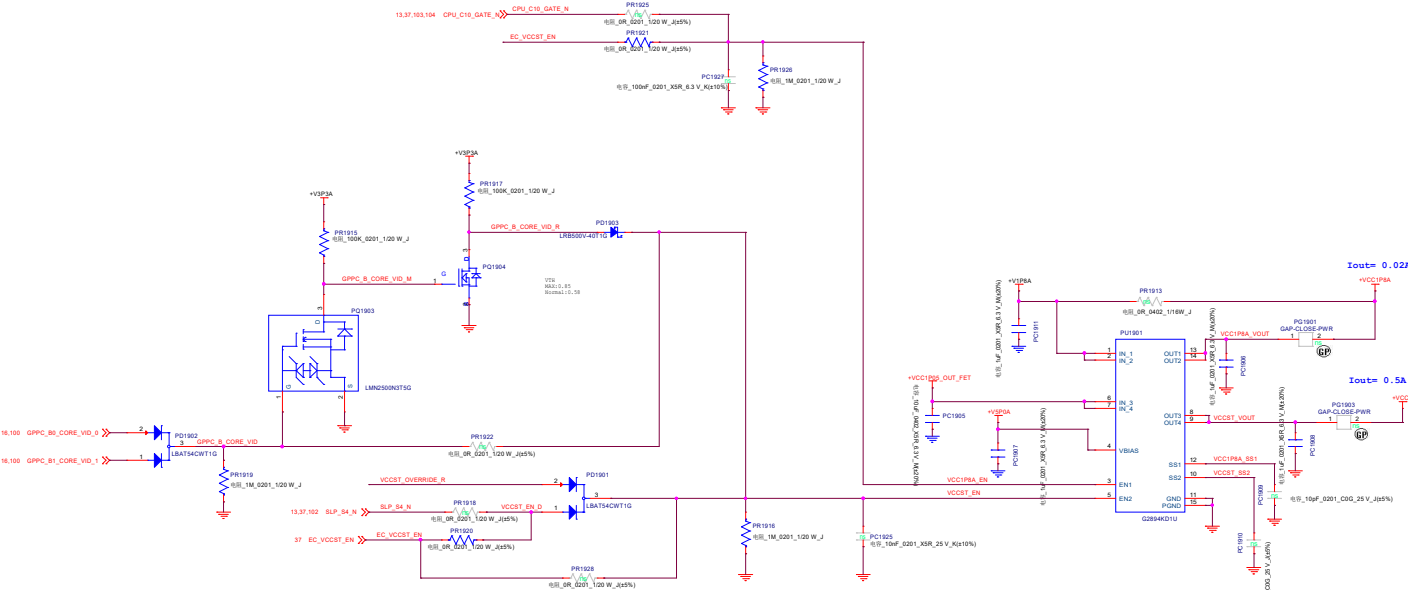
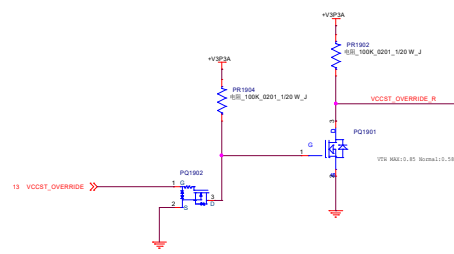
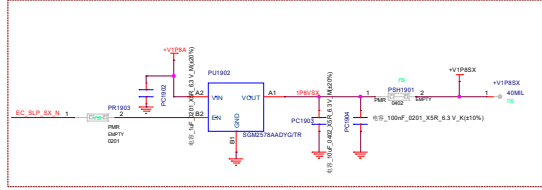
PIN SETTING	FUNCTION1	FUNCTION2	FUNCTION3
SET1	EN_LV_HIGH	VBOOT	ICCMAX
SET2	AKTIOVS_TH	AI_GAIN	NA
SET3	OR_TN_DISABLE	NA	NA
TSEN	DVID_LIFT_DISABLE	VR_HOT @100DEG	



VSP0A\_PGOOD << VSP0A\_PGOOD 37,97,99,100,102,103  
VCC\_DDR\_PWR0K << VCC\_DDR\_PWR0K 13,37,102  
SLP\_S4\_N << SLP\_S4\_N 13,37,102,104  
EC\_VDDQ\_EN << EC\_VDDQ\_EN 37,102



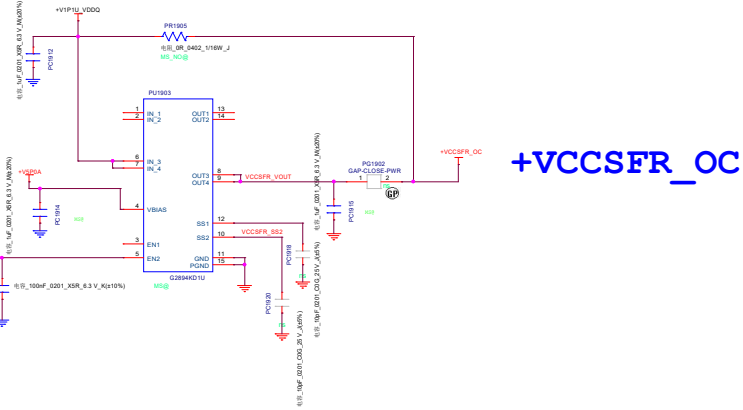
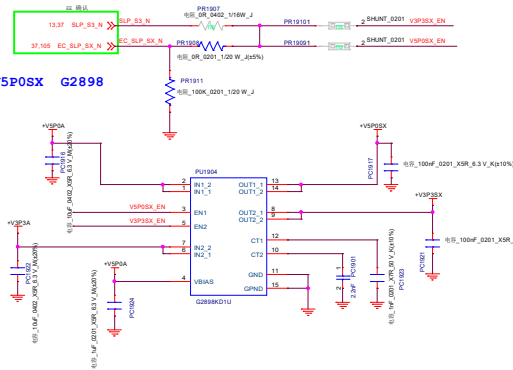




**+VCC1P8A**

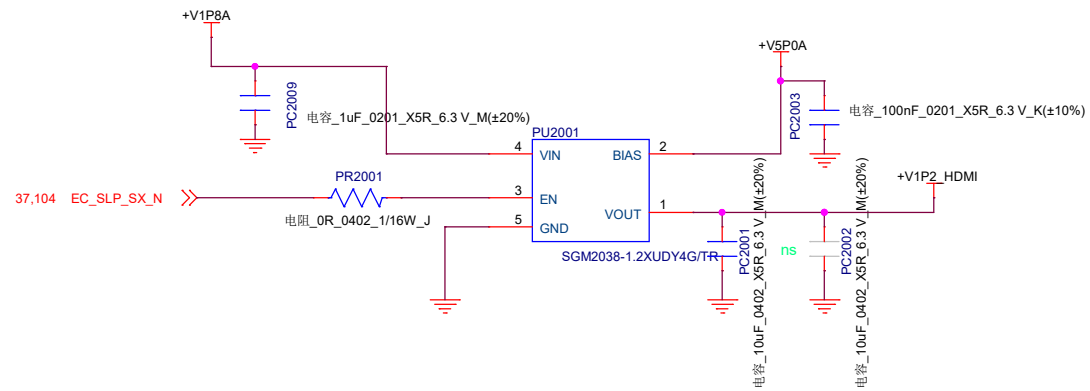
**+VCCST**

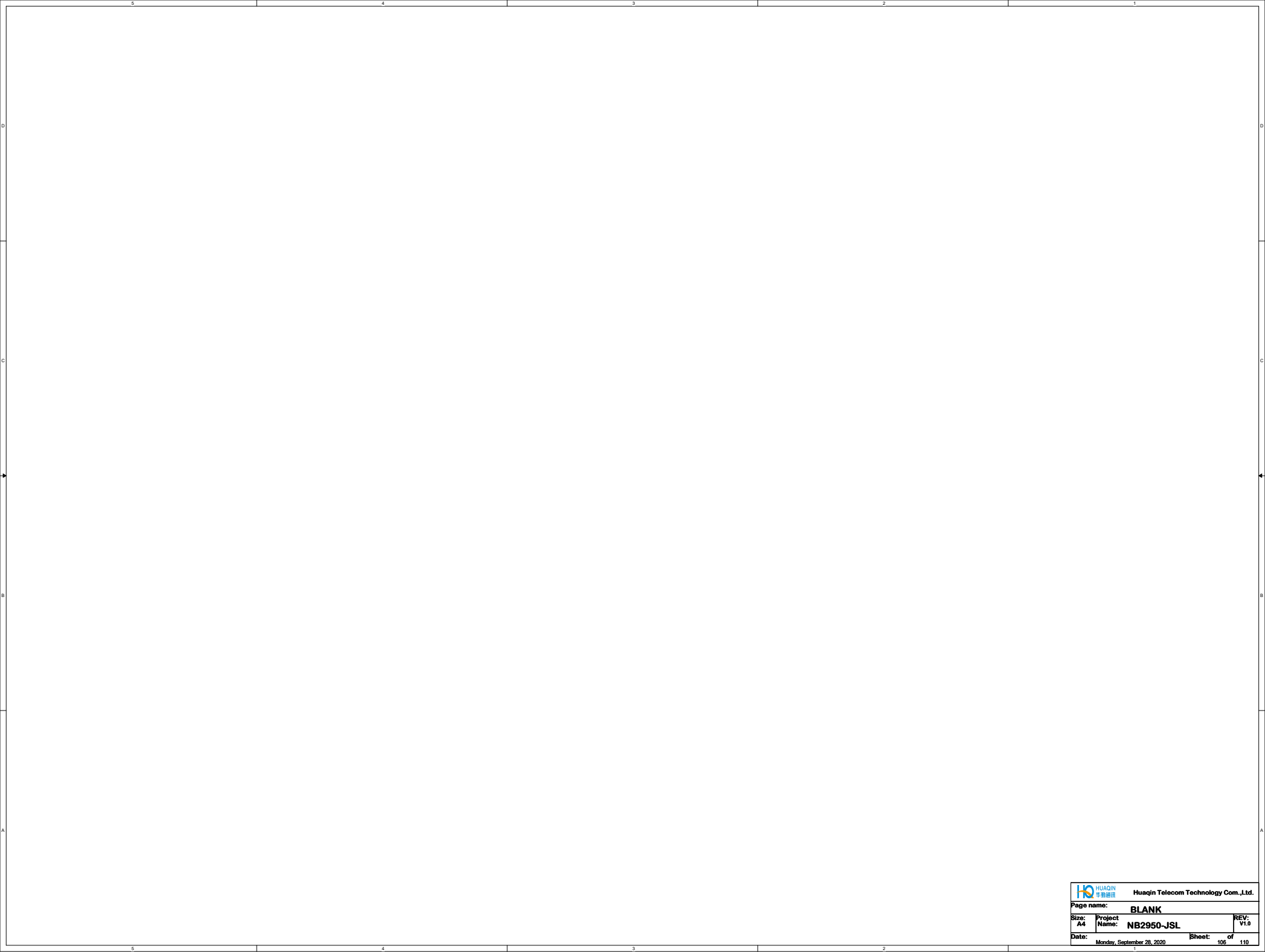
**+V3P3SX, +V5P0SX G2898**



**+VCCSFR\_OC**







5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1





